

HP ProLiant DL160 Gen9 Server Maintenance and Service Guide

Abstract

This guide describes identification and maintenance procedures, diagnostic tools, specifications and requirements for hardware components and software.



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Contents

Customer self repair	6
Parts only warranty service.....	6
Illustrated parts catalog	16
Mechanical components	16
System components	18
Removal and replacement procedures	23
Required tools.....	23
Safety considerations.....	23
Preventing electrostatic discharge	23
Symbols on equipment.....	23
Server warnings and cautions.....	24
Rack warnings	25
Preparation procedures.....	25
Power down the server	26
Remove the security bezel (optional).....	26
Non-hot-plug drive.....	27
Hot-plug drive blanks.....	27
Extend the server from the rack.....	28
Remove the server from the rack	29
Non-hot-plug drive carrier	29
Hot-plug drive	30
Access panel	30
Four-bay LFF hot-plug drive backplane.....	31
Four-bay LFF non-hot-plug drive backplane.....	32
Eight-bay LFF hot-plug drive backplane	33
HP Smart Storage Battery.....	34
FBWC module	35
Optical drive	36
Fan and fan blank.....	38
Fan population guidelines	38
Fan blank.....	39
Hot-swap fan	40
DIMMs.....	41
Heatsink.....	42
Processor.....	44
Expansion board.....	48
Primary PCIe riser board	49
Secondary PCIe riser board	50
System battery	51
Dedicated iLO management module	52
Front I/O modules for LFF and SFF drive models.....	53
System board	55
HP 550-W Power Supply	62
HP Trusted Platform Module.....	63

Troubleshooting	64
Troubleshooting resources	64
Diagnostic tools	65
HP UEFI System Utilities.....	65
Using HP UEFI System Utilities	65
Flexible boot control	66
Restoring and customizing configuration settings	66
Secure Boot configuration	66
Embedded UEFI shell	67
Embedded Diagnostics option	67
HP RESTful API support for UEFI	67
Re-entering the server serial number and product ID.....	67
HP ProLiant Pre-boot Health Summary.....	68
HP Insight Diagnostics	68
HP Insight Diagnostics survey functionality	68
Active Health System	69
Integrated Management Log.....	70
USB support	70
External USB functionality	70
Internal USB functionality	70
Component identification.....	71
Front panel components.....	71
Front panel LEDs and buttons.....	72
Power fault LEDs.....	73
Rear panel components	74
Rear panel LEDs.....	75
PCIe riser board slot definitions	75
System board components	76
DIMM slot locations.....	77
System maintenance switch	77
NMI functionality	78
Drive numbering	78
HP SmartDrive LED definitions.....	79
Fan locations	80
Cabling	81
Cabling overview.....	81
Storage cabling	81
Four-bay LFF non-hot-plug drive cabling	81
Four-bay LFF hot-plug drive cabling	82
Eight-bay SFF hot-plug drive cabling.....	83
FBWC cabling.....	85
HP Smart Storage Battery cabling	86
HP 550W Power Supply cabling (non-hot plug)	87
Optical drive cabling.....	87
Front I/O cabling.....	88
Front USB 3.0 cabling	89
Specifications.....	90
Environmental specifications.....	90
Mechanical specifications	90
Power supply specifications.....	91

Acronyms and abbreviations.....	92
Documentation feedback.....	95
Index.....	96

Customer self repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Parts only warranty service

Your HP Limited Warranty may include a parts only warranty service. Under the terms of parts only warranty service, HP will provide replacement parts free of charge.

For parts only warranty service, CSR part replacement is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Service de garantie "pièces seules"

Votre garantie limitée HP peut inclure un service de garantie "pièces seules". Dans ce cas, les pièces de rechange fournies par HP ne sont pas facturées.

Dans le cadre de ce service, la réparation des pièces CSR par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Servizio di garanzia per i soli componenti

La garanzia limitata HP può includere un servizio di garanzia per i soli componenti. Nei termini di garanzia del servizio per i soli componenti, HP fornirà gratuitamente le parti di ricambio.

Per il servizio di garanzia per i soli componenti è obbligatoria la formula CSR che prevede la riparazione da parte del cliente. Se il cliente invece richiede la sostituzione ad HP, dovrà sostenere le spese di spedizione e di manodopera per il servizio.

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das

defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Parts-only Warranty Service (Garantieservice ausschließlich für Teile)

Ihre HP Garantie umfasst möglicherweise einen Parts-only Warranty Service (Garantieservice ausschließlich für Teile). Gemäß den Bestimmungen des Parts-only Warranty Service stellt HP Ersatzteile kostenlos zur Verfügung.

Für den Parts-only Warranty Service ist das CSR-Verfahren zwingend vorgegeben. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no

enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Servicio de garantía exclusivo de componentes

La garantía limitada de HP puede que incluya un servicio de garantía exclusivo de componentes. Según las condiciones de este servicio exclusivo de componentes, HP le facilitará los componentes de repuesto sin cargo adicional alguno.

Para este servicio de garantía exclusivo de componentes, es obligatoria la sustitución de componentes por parte del usuario (CSR). Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Garantieservice "Parts Only"

Het is mogelijk dat de HP garantie alleen de garantieservice "Parts Only" omvat. Volgens de bepalingen van de Parts Only garantieservice zal HP kosteloos vervangende onderdelen ter beschikking stellen.

Voor de Parts Only garantieservice is vervanging door CSR-onderdelen verplicht. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

Serviço de garantia apenas para peças

A garantia limitada da HP pode incluir um serviço de garantia apenas para peças. Segundo os termos do serviço de garantia apenas para peças, a HP fornece as peças de reposição sem cobrar nenhuma taxa.

No caso desse serviço, a substituição de peças CSR é obrigatória. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

カスタマーセルフリペア

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数のCSR部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須** - カスタマーセルフリペアが必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意** - カスタマーセルフリペアが任意である部品。この部品もカスタマーセルフリペア用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注： HP製品の一部の部品は、カスタマーセルフリペア用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品がカスタマーセルフリペア除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口へ電話していただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。カスタマーセルフリペアの際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

部品のみ保証サービス

HP保証サービスには、部品のみ保証サービスが適用される場合があります。このサービスでは、交換部品は無償で提供されます。

部品のみ保証サービスにおいては、CSR部品をお客様により交換作業していただくことが必須となります。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費はお客様の負担となります。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在规定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

仅部件保修服务

您的 HP 有限保修服务可能涉及仅部件保修服务。根据仅部件保修服务条款的规定，HP 将免费提供更换的部件。

仅部件保修服务要求进行 CSR 部件更换。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

僅限零件的保固服務

您的「HP 有限保固」可能包含僅限零件的保固服務。在僅限零件的保固服務情況下，HP 將免費提供替換零件。

針對僅限零件的保固服務，CSR 零件替換是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 용통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

참고: 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

부품 제공 보증 서비스

HP 제한 보증에는 부품 제공 보증 서비스가 포함될 수 있습니다. 이러한 경우 HP는 부품 제공 보증 서비스의 조건에 따라 교체 부품만을 무료로 제공합니다.

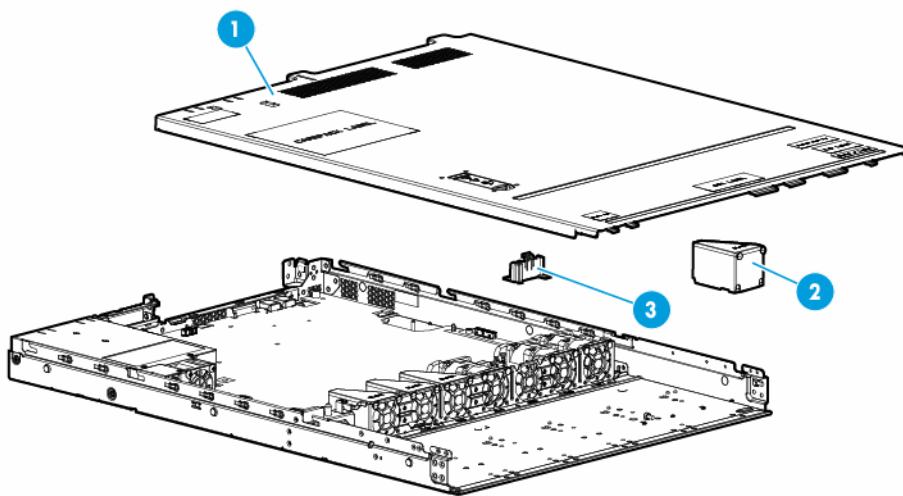
부품 제공 보증 서비스 제공 시 CSR 부품 교체는 의무 사항입니다. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

Illustrated parts catalog

Mechanical components

HP continually improves and changes product parts. For complete and current supported parts information, see one of the following websites:

- HP PartSurfer website (<http://partsurfer.hp.com>)
- HP PartSurfer mobile site (<http://partsurfermobile.hp.com>)



Item	Description	Spare part number	Customer self repair (on page 6)
1	Access panel	779099-001	Mandatory ¹
2	Fan blank	779105-001	Mandatory ¹
3	HP Smart Storage Battery holder	779102-001	Mandatory ¹

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese addizionali a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

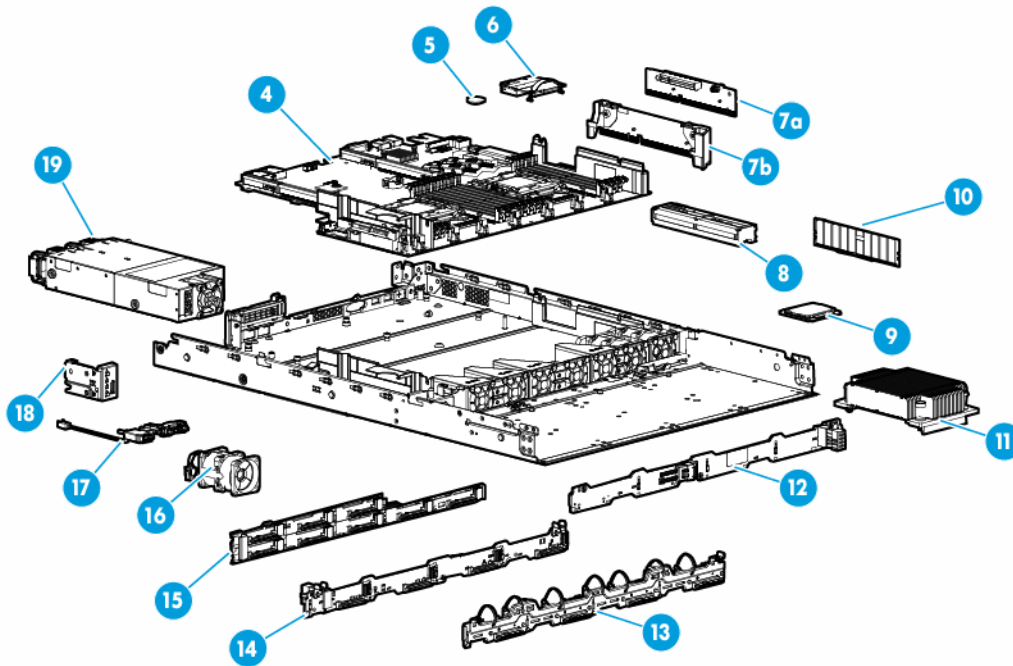
³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

System components

HP continually improves and changes product parts. For complete and current supported parts information, see one of the following websites:

- HP PartSurfer website (<http://partsurfer.hp.com>)

- HP PartSurfer mobile site (<http://partsurfermobile.hp.com>)



Item	Description	Spare part number	Customer self repair (on page 6)
4	System board assembly (includes alcohol pad and thermal compound)	779094-001	Mandatory ¹
5	System Battery	234556-001	Optional ²
6	Dedicated iLO management module	779095-001	Mandatory ¹
7	PCIe riser boards	—	—
	a) Primary PCIe riser board	779098-001	Mandatory ¹
	b) Secondary PCIe riser board assembly	779106-001	Mandatory ¹
8	HP Smart Storage Battery	750450-001	Mandatory ¹
9	Processors (include alcohol pad and thermal compound)	—	—
	a) 1.6-GHz Intel Xeon E5-2603 v3, 6C, 85 W*	762441-001	Optional ²
	b) 1.8-GHz Intel Xeon E5-2630L v3, 8C, 55W*	762459-001	Optional ²
	c) 1.8-GHz Intel Xeon E5-2650L v3, 12C 65 W*	762461-001	Optional ²
	d) 1.9-GHz Intel Xeon E5-2609 v3, 6C, 85 W*	762443-001	Optional ²
	e) 2.3-GHz Intel Xeon E5-2650 v3, 10C, 105 W*	762448-001	Optional ²
	f) 2.4-GHz Intel Xeon E5-2620 v3, 6C, 85 W*	762445-001	Optional ²
	g) 2.4-GHz Intel Xeon E5-2630 v3, 8C, 85 W*	762446-001	Optional ²
	h) 2.6-GHz Intel Xeon E5-2640 v3, 8C, 90 W*	762447-001	Optional ²
	i) 2.6-GHz Intel Xeon E5-2660 v3, 10C, 105 W*	762449-001	Optional ²
10	DIMMs	—	—

Item	Description	Spare part number	Customer self repair (on page 6)
	a) 8 GB, single-rank 1Rx4 PC4-2133R-15*	774170-001	Mandatory ¹
	b) 16 GB, dual-rank 2Rx4 PC4-2133R-15*	774172-001	Mandatory ¹
	c) 32 GB, quad-rank 4Rx4 PC4-2133P-L*	774174-001	Mandatory ¹
11	Heatsink	779104-001	Optional ²
12	4-bay LFF hot plug drive backplane	779096-001	Optional ²
13	4-bay LFF non-hot-plug drive backplane assembly	779107-001	Optional ²
14	4-bay LFF hot plug drive backplane assembly	779108-001	Optional ²
15	8-bay SFF hot plug drive backplane	779097-001	Optional ²
16	Hot-swap fan	779103-001	Mandatory ¹
17	Front I/O module for LFF drive models	779100-001	Optional ²
18	Front I/O module for SFF drive models	779100-001	Optional ²
19	HP 550-W Power Supply	766879-001	Optional ²
20	Cables	—	—
	a) 20-pin power cable for SFF drive models*	782422-001	Mandatory ¹
	b) 8-bay SFF SATA cable*	782423-001	Mandatory ¹
	c) Front USB 3.0 module*	782424-001	Mandatory ¹
	d) 4-bay LFF hot-plug power cable*	782425-001	Mandatory ¹
	e) 4-bay LFF SATA cable*	782426-001	Mandatory ¹
	f) 4-bay LFF non-hot-plug drive cable*	782427-001	Mandatory ¹
	g) 4-bay LFF Smart Array controller mini-SAS cable*	782428-001	Mandatory ¹
	h) 4-bay LFF HBA mini-SAS cable*	782429-001	Mandatory ¹
	i) 8-bay SFF Smart Array controller mini-SAS cable*	782430-001	Mandatory ¹
	j) 8-bay SFF HBA mini-SAS cable*	782431-001	Mandatory ¹
21	Trusted Platform Module*	505836-001	No ³

* Not shown

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

Removal and replacement procedures

Required tools

You need the following items for some procedures:

- T-25 Torx screwdriver (for screws located inside the front panel quick-release levers)
- T-10/T-15 Torx screwdriver
- HP Insight Diagnostics (on page 68)

Safety considerations

Before performing service procedures, review all the safety information.

Preventing electrostatic discharge

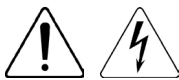
To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Symbols on equipment

The following symbols may be placed on equipment to indicate the presence of potentially hazardous conditions.



This symbol indicates the presence of hazardous energy circuits or electric shock hazards. Refer all servicing to qualified personnel.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure. Refer all maintenance, upgrades, and servicing to qualified personnel.



This symbol indicates the presence of electric shock hazards. The area contains no user or field serviceable parts. Do not open for any reason.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure.



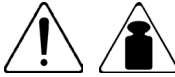
This symbol on an RJ-45 receptacle indicates a network interface connection.

WARNING: To reduce the risk of electric shock, fire, or damage to the equipment, do not plug telephone or telecommunications connectors into this receptacle.



This symbol indicates the presence of a hot surface or hot component. If this surface is contacted, the potential for injury exists.

WARNING: To reduce the risk of injury from a hot component, allow the surface to cool before touching.



This symbol indicates that the component exceeds the recommended weight for one individual to handle safely.

WARNING: To reduce the risk of personal injury or damage to the equipment, observe local occupational health and safety requirements and guidelines for manual material handling.



These symbols, on power supplies or systems, indicate that the equipment is supplied by multiple sources of power.

WARNING: To reduce the risk of injury from electric shock, remove all power cords to completely disconnect power from the system.

Server warnings and cautions



WARNING: This server is very heavy. To reduce the risk of personal injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual material handling.
- Get help to lift and stabilize the product during installation or removal, especially when the product is not fastened to the rails. HP recommends that a minimum of two people are required for all rack server installations. A third person may be required to help align the server if the server is installed higher than chest level.
- Use caution when installing the server in or removing the server from the rack; it is unstable when not fastened to the rails.



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



CAUTION: Protect the server from power fluctuations and temporary interruptions with a regulating uninterruptible power supply. This device protects the hardware from damage caused by power surges and voltage spikes and keeps the system in operation during a power failure.



CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

Rack warnings

-
- ⚠ **WARNING:** To reduce the risk of personal injury or damage to the equipment, be sure that:
 - The leveling jacks are extended to the floor.
 - The full weight of the rack rests on the leveling jacks.
 - The stabilizing feet are attached to the rack if it is a single-rack installation.
 - The racks are coupled together in multiple-rack installations.
 - Only one component is extended at a time. A rack may become unstable if more than one component is extended for any reason.
-
- ⚠ **WARNING:** To reduce the risk of personal injury or equipment damage when unloading a rack:
 - At least two people are needed to safely unload the rack from the pallet. An empty 42U rack can weigh as much as 115 kg (253 lb), can stand more than 2.1 m (7 ft) tall, and might become unstable when being moved on its casters.
 - Never stand in front of the rack when it is rolling down the ramp from the pallet. Always handle the rack from both sides.
-
- ⚠ **WARNING:** To reduce the risk of personal injury or damage to the equipment, adequately stabilize the rack before extending a component outside the rack. Extend only one component at a time. A rack may become unstable if more than one component is extended.
-
- ⚠ **WARNING:** When installing a server in a telco rack, be sure that the rack frame is adequately secured at the top and bottom to the building structure.
-

Preparation procedures

To access some components and perform certain service procedures, you must perform one or more of the following procedures:

- Access the product front panel ("[Remove the security bezel \(optional\)](#)" on page 26).
- Power down the server (on page 26).

If you must remove a server from a rack or a non-hot-plug component from a server, power down the server.
- Extend the server from the rack (on page 28).

If you are performing service procedures in an HP, Compaq branded, Telco, or third-party rack cabinet, you can use the locking feature of the rack rails to support the server and gain access to internal components.

For more information about Telco rack solutions, see the RackSolutions website (<http://www.racksolutions.com/hp>).
- Access the product rear panel.
- Remove the server from the rack (on page 29).

If the rack environment, cabling configuration, or the server location in the rack creates awkward conditions, remove the server from the rack.

Power down the server

Before powering down the server for any upgrade or maintenance procedures, perform a backup of critical server data and programs.

⚠ WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC/DC power is removed.

📝 IMPORTANT: When the server is in standby mode, auxiliary power is still being provided to the system.

To power down the server, use one of the following methods:

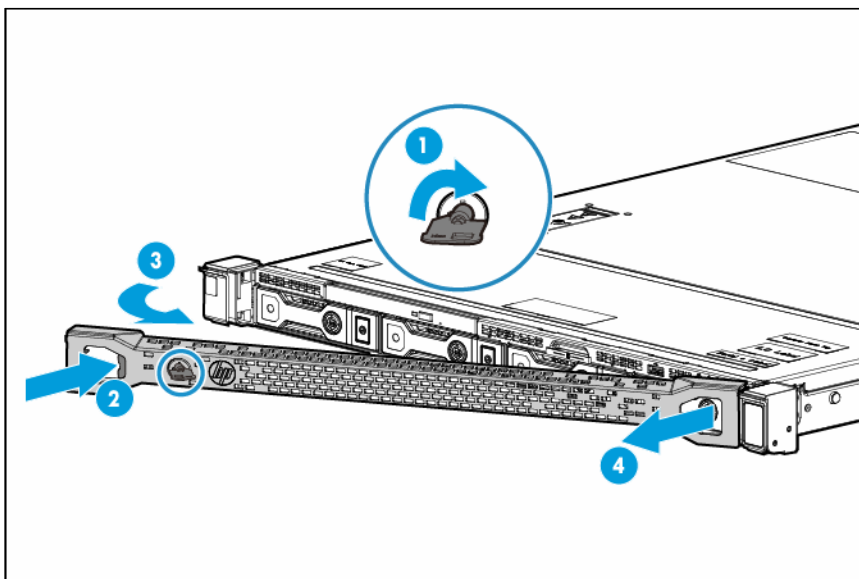
- Press and release the Power On/Standby button.
This method initiates a controlled shutdown of applications and the OS before the server enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server to enter standby mode.
This method forces the server to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through Dedicated iLO management.
This method initiates a controlled remote shutdown of applications and the OS before the server enters standby mode.

Before proceeding, verify the server is in standby mode by observing that the system power LED is amber.

Remove the security bezel (optional)

The security bezel is only supported in servers using the quick-release latch rack ears.

To access the front panel components, unlock and then remove the security bezel.

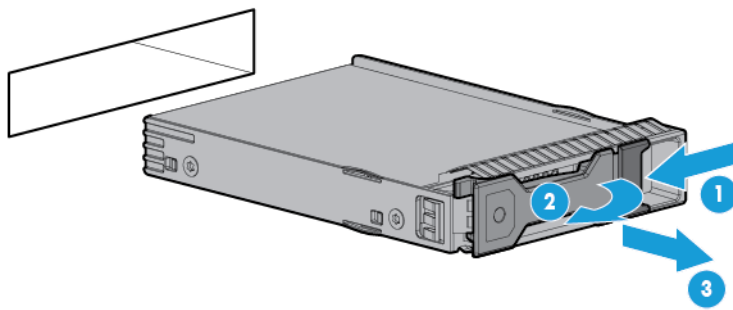


Non-hot-plug drive

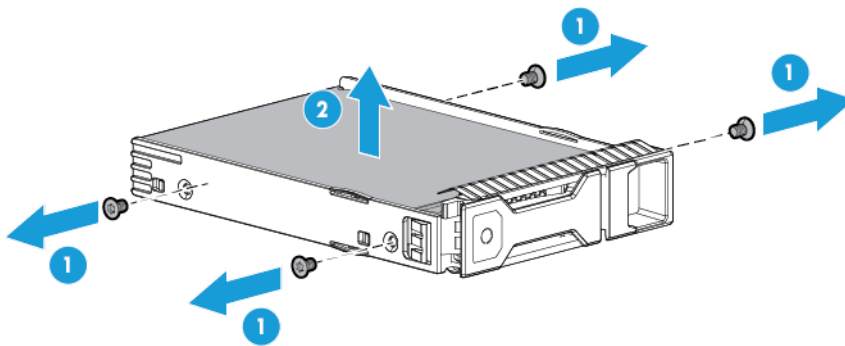
- △ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Back up all server data on the drive.
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Remove the non-hot-plug drive.



5. Remove the drive from the carrier.



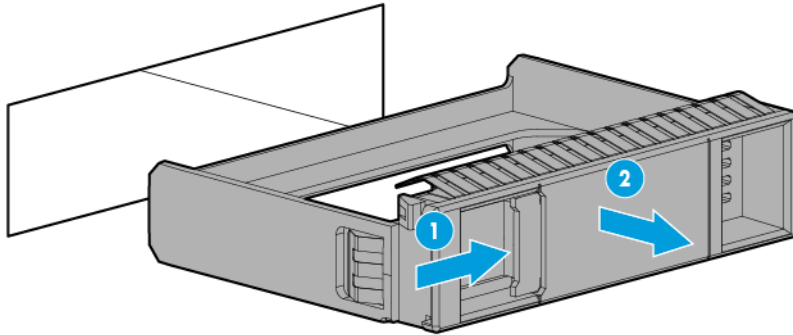
To replace the component, reverse the removal procedure.

Hot-plug drive blanks

- △ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

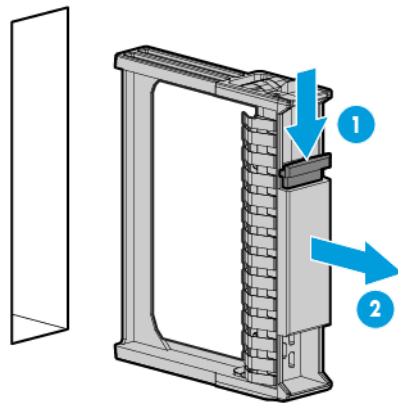
To remove the component:

- Hot-plug LFF drive blank



To replace the LFF drive blank, slide the component into the bay until it clicks.

- Hot-plug SFF drive blank



To replace the SFF drive blank, while pressing the release latch, slide the component into the bay until it is fully seated.

Extend the server from the rack

To extend the server from an HP, Compaq-branded, Telco, or third-party rack:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Disconnect all peripheral cables from the server.

⚠ WARNING: To reduce the risk of personal injury or equipment damage, be sure that the rack is adequately stabilized before extending a component from the rack.

⚠ WARNING: To reduce the risk of personal injury, be careful when pressing the server rail-release latches and sliding the server into the rack. The sliding rails could pinch your fingers.

4. Do one of the following:

- In a server that uses thumbscrew rack ears, loosen the captive thumbscrews that secure the server faceplate to the front of the enclosure, and then slide the server out of the enclosure.
- In a server that uses quick-release latch rack ears:
 - i. Open the latches on both sides of the server.
 - ii. If necessary, use a T-25 Torx screwdriver to loosen the shipping screws.
 - iii. Slide the server out of the enclosure.
- 5. After performing the installation or maintenance procedure, slide the server back into the enclosure, and then press the server firmly into the enclosure to secure it in place.
- 6. Connect the peripheral cables.
- 7. Connect each power cord to the server.
- 8. Connect each power cord to the power source.

Remove the server from the rack



WARNING: This server is very heavy. To reduce the risk of personal injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual material handling.
- Get help to lift and stabilize the product during installation or removal, especially when the product is not fastened to the rails. HP recommends that a minimum of two people are required for all rack server installations. A third person may be required to help align the server if the server is installed higher than chest level.
- Use caution when installing the server in or removing the server from the rack; it is unstable when not fastened to the rails.

To remove the server from an HP, Compaq-branded, Telco, or a third-party enclosure:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Disconnect all peripheral cables from the server.
4. Remove the server from the rack.

For instructions on how to extend or remove the server from the rack, see the documentation that ships with the rack rail system.

5. Place the server on a sturdy, level surface.

Non-hot-plug drive carrier

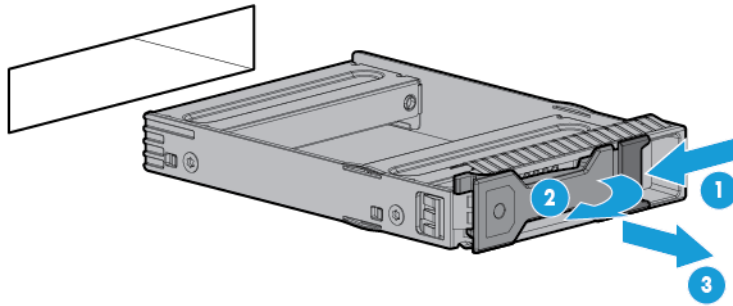


CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:

- a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Remove the drive carrier.



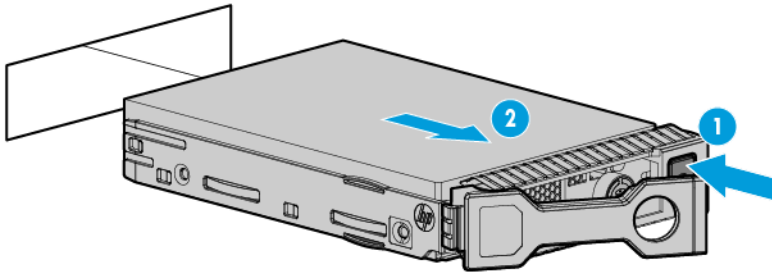
To replace the component, slide the component into the bay until it clicks.

Hot-plug drive

CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Back up all server data on the drive.
2. Determine the status of the drive from the drive LED definitions.
3. Remove the hot-plug drive.



To replace the component, reverse the removal procedure.

Access panel

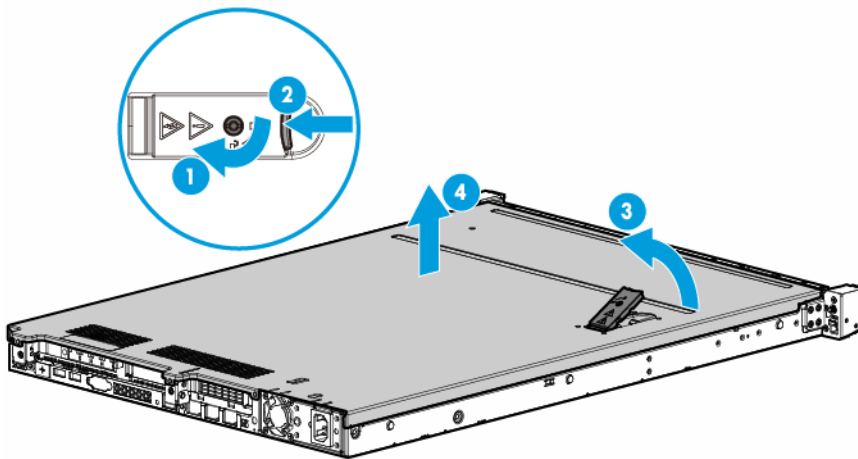
To remove the component:

WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Open the access panel latch, slide the access panel to the rear of the chassis, and then remove the access panel.

If the access panel latch is locked, use a T-15 Torx screwdriver to unlock the latch.



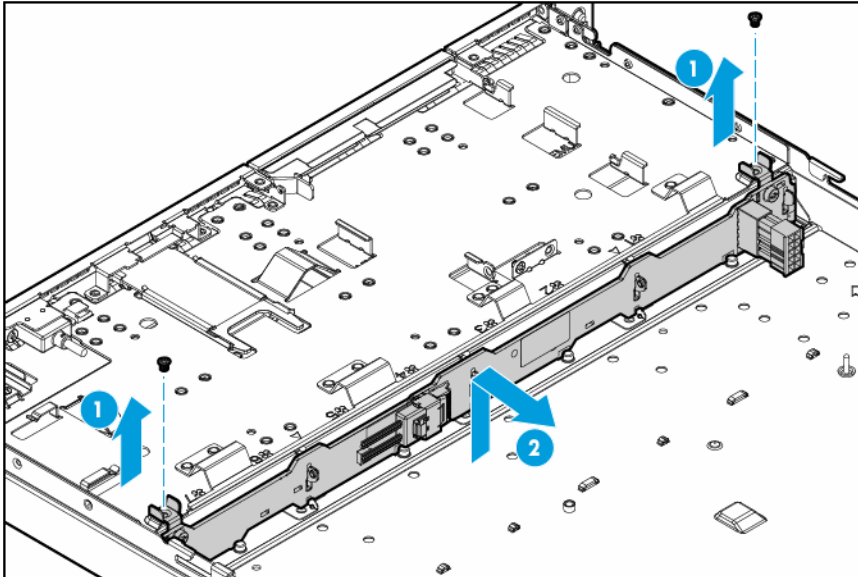
To replace the component, reverse the removal procedure.

Four-bay LFF hot-plug drive backplane

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).

5. Remove all hot-plug hard drives.
6. Disconnect all cables connected to the drive backplane.
7. Remove the hot-plug drive backplane.



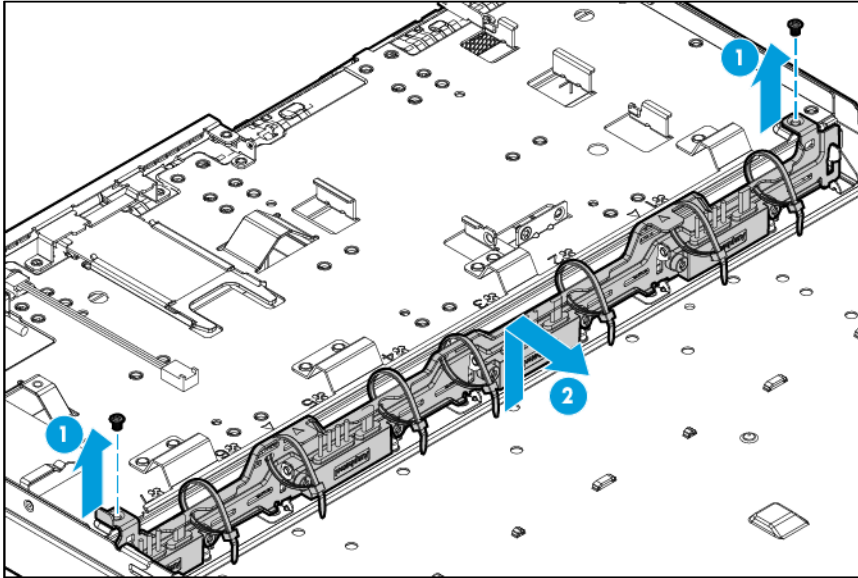
To replace the component, reverse the removal procedure.

Four-bay LFF non-hot-plug drive backplane

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove all non-hot plug drives. ("Non-hot-plug drive" on page 27, "Non-hot-plug drive carrier" on page 29)
6. Disconnect all cables connected to the drive backplane.

7. Remove the non-hot-plug drive backplane.



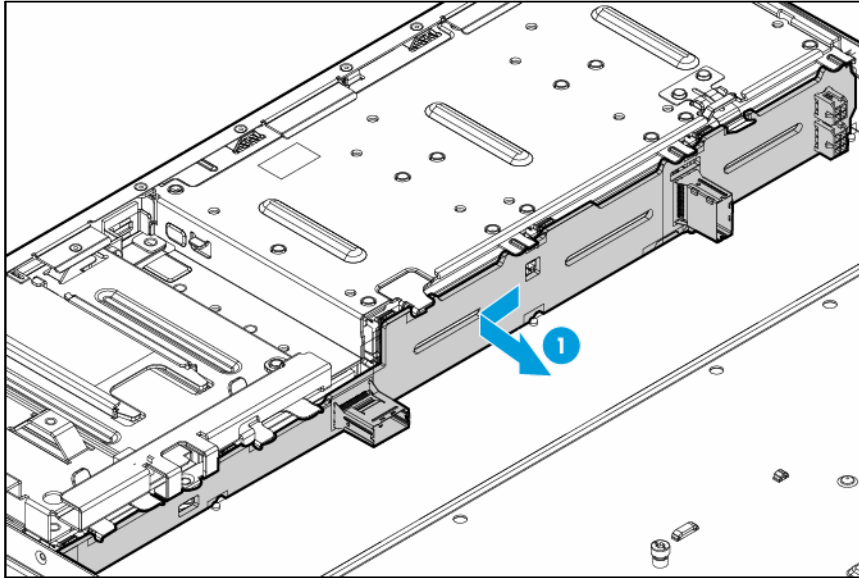
To replace the component, reverse the removal procedure.

Eight-bay LFF hot-plug drive backplane

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove all hot-plug hard drives.
6. Disconnect all cables connected to the drive backplane.

7. Remove the hot-plug drive backplane.



To replace the component, reverse the removal procedure.

HP Smart Storage Battery

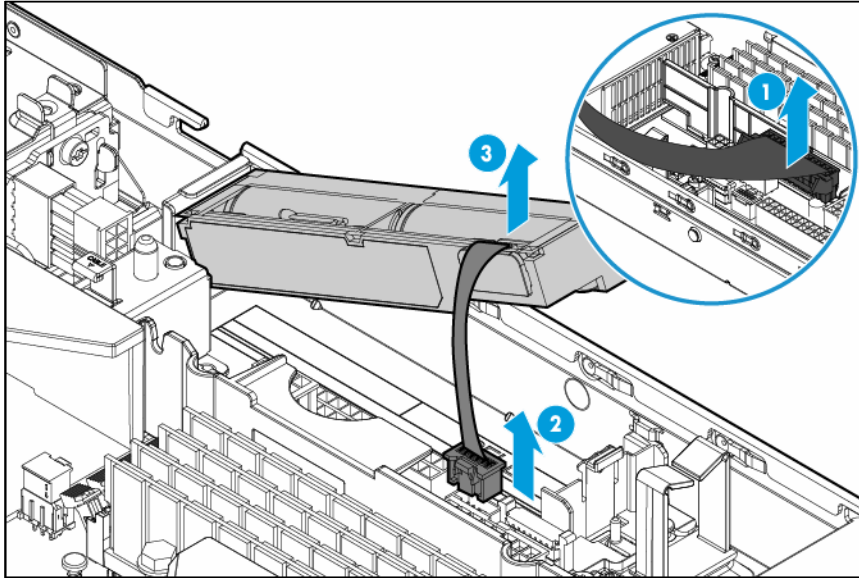
For more information about product features, specifications, options, configurations, and compatibility, see the product QuickSpecs on the HP website (<http://www.hp.com/go/qs>).

CAUTION: In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the external drives as failed when the server is powered up.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Disconnect the 24-pin power supply cable from the system board.
6. Disconnect the Smart Storage Battery cable from the system board.

7. Remove the HP Smart Storage Battery.



To replace the component, reverse the removal procedure.

FBWC module

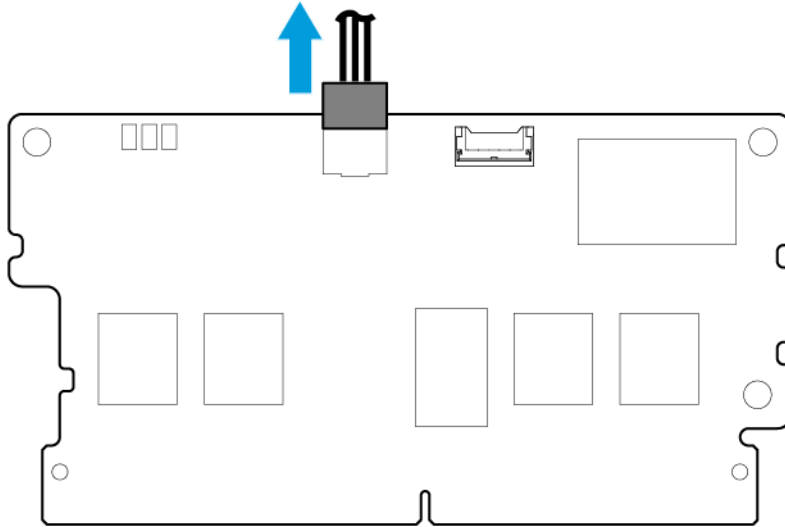
-
- ⚠ **WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.
-
- ⚠ **CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.
-
- ⚠ **CAUTION:** To prevent damage to electrical components, take the appropriate anti-static precautions before beginning any installation, removal, or replacement procedure. Improper grounding can cause electrostatic discharge.
-

To remove the component:

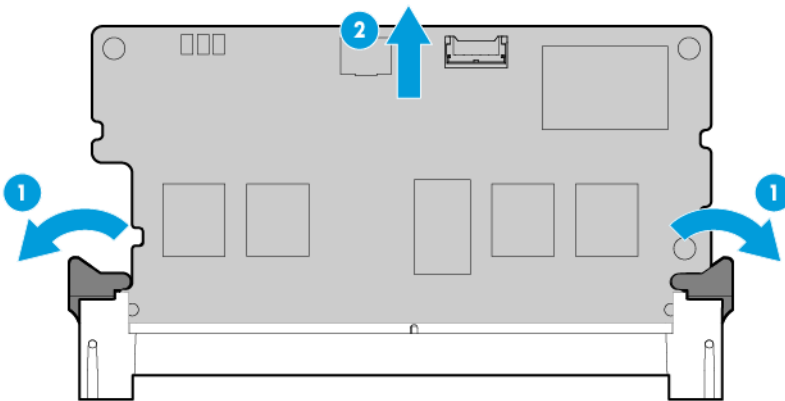
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - Extend the server from the rack (on page 28).
 - Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).

- ⚠ **CAUTION:** When connecting or disconnecting the cache module cable, the connectors on the cache module and cable are susceptible to damage. Avoid excessive force and use caution to avoid damage to these connectors.
-

5. Disconnect the cache module backup power cable from the cache module.



6. Remove the cache module.



To replace the component, reverse the removal procedure.

Optical drive

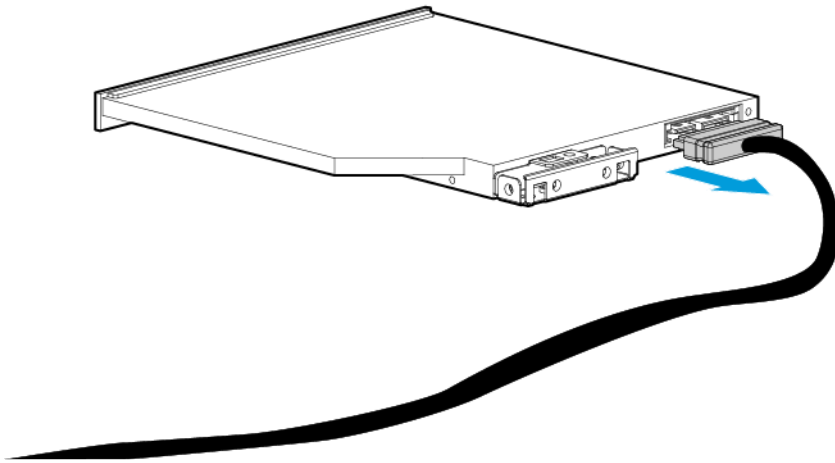


CAUTION: To prevent improper cooling and thermal damage, do not operate the chassis unless all bays are populated with a component or a blank.

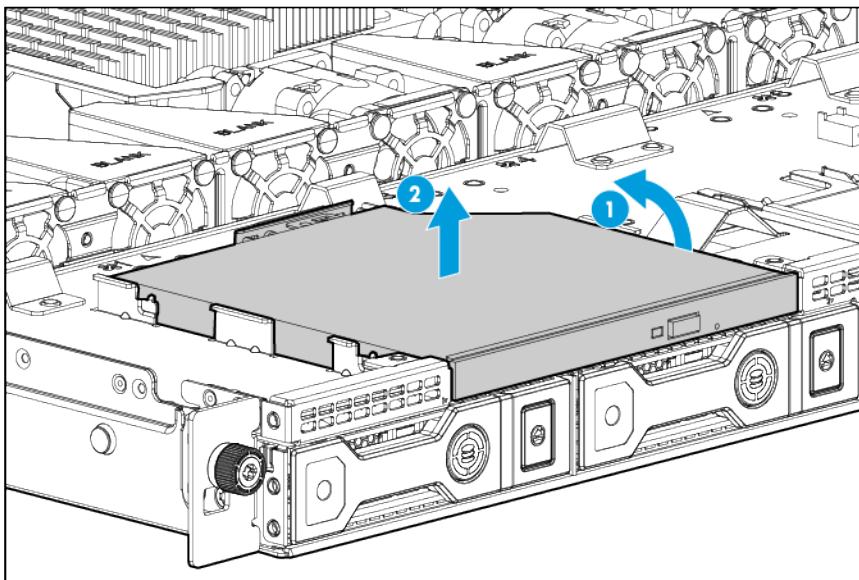
To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).

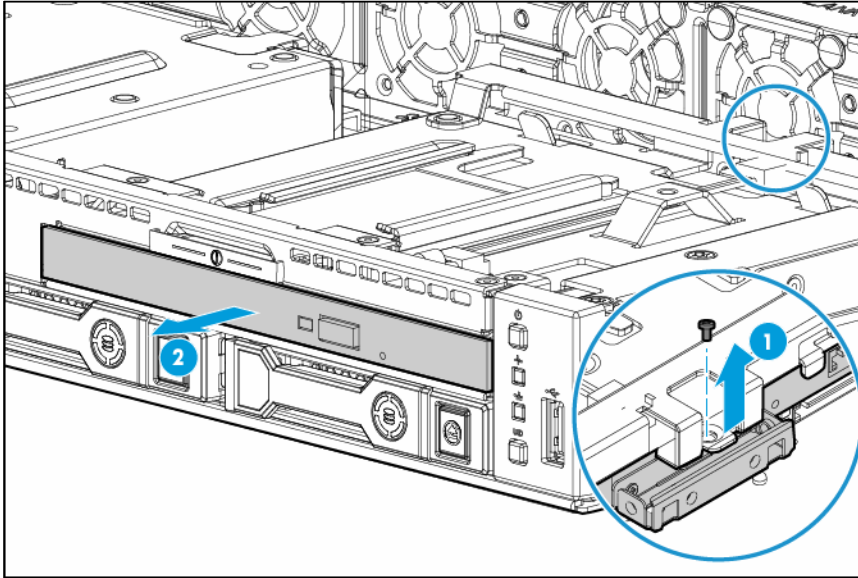
- Remove the server from the rack (on page 29).
- 4. Remove the access panel ("Access panel" on page 30).
- 5. Disconnect the optical drive cable from the drive.



- 6. Remove the optical drive:
 - Four-bay LFF drive model



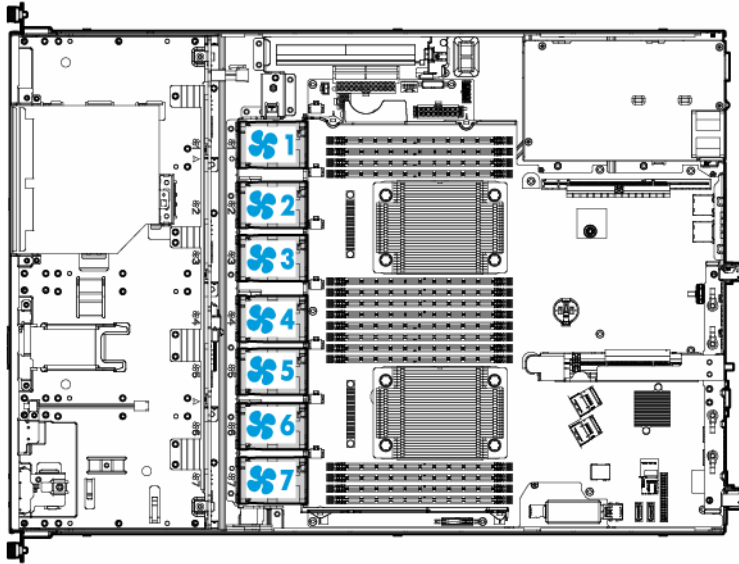
- o Eight-bay SFF drive model



To replace the component, reverse the removal procedure.

Fan and fan blank

Fan population guidelines



Configuration	Fan bay 1	Fan bay 2	Fan bay 3	Fan bay 4	Fan bay 5	Fan bay 6	Fan bay 7
One processor, non-redundant	Blank	Blank	Blank	Fan	Blank	Fan	Fan
One processor, redundant	Blank	Blank	Blank	Fan	Fan	Fan	Fan
Two processors, non-redundant	Fan	Fan	Fan	Blank	Fan	Fan	Fan

Two processors, redundant	Fan	Fan	Fan	Fan	Fan	Fan	Fan
------------------------------	-----	-----	-----	-----	-----	-----	-----

- In a single-processor, nonredundant configuration, fans 4, 6, and 7 cool the server. To enable the redundant fan mode, install a new fan in the fan bay 5.
- In a dual-processor, nonredundant configuration, fans 1, 2, 3, 5, 6, and 7 cool the server. To enable the redundant fan mode, install a new fan in the fan bay 4.
- In the redundant fan mode:
 - If one fan rotor fails, the system continues to operate without redundancy. This condition is indicated by a flashing amber Health LED.
 - If two fan rotors fail, the system shuts down.
- The minimum fan requirement to make this server bootable is three fans for a single processor and six fans for a dual processor configuration.

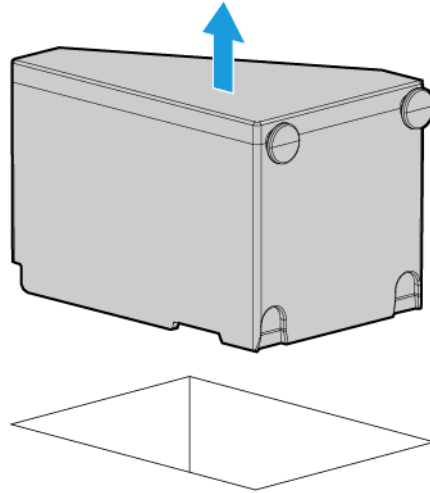
Fan blank



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

1. Press the Power On/Standby button.
2. The server powers down and enters standby mode. The system power LED changes from green to amber. Power is still applied to the server.
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Disconnect all peripheral cables and power cords from the rear panel.
5. Do one of the following:
 - Extend the server from the rack (on page 28).
 - Remove the server from the rack (on page 29).
6. Remove the access panel ("Access panel" on page 30).

7. Remove the fan blank.



-
- CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.
-

To replace the component, reverse the removal procedure.

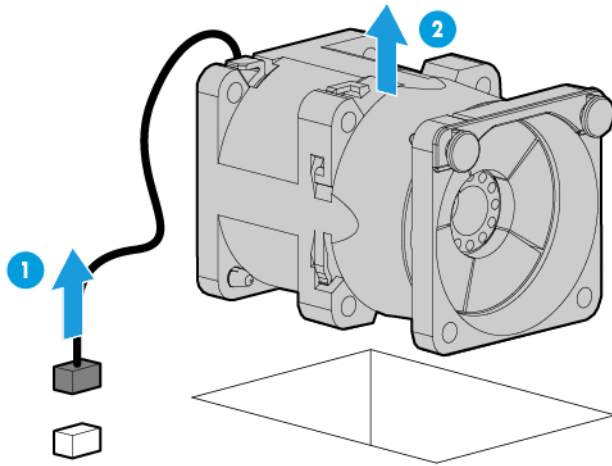
Hot-swap fan

-
- WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.
-
- CAUTION:** To prevent damage to electrical components, properly ground the server before beginning any installation procedure. Improper grounding can cause ESD.
-

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).

5. Disconnect the fan cable from the system board and remove the fan.



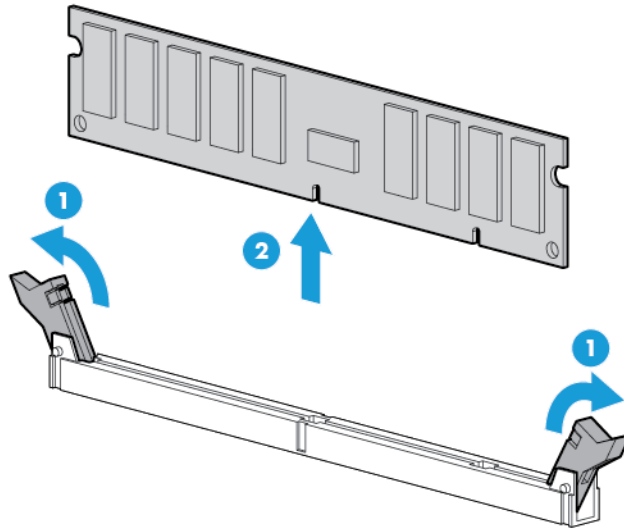
To replace the component, reverse the removal procedure.

DIMMs

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Open the DIMM slot latches.

6. Remove the DIMM.



To replace the component, reverse the removal procedure.

Heatsink

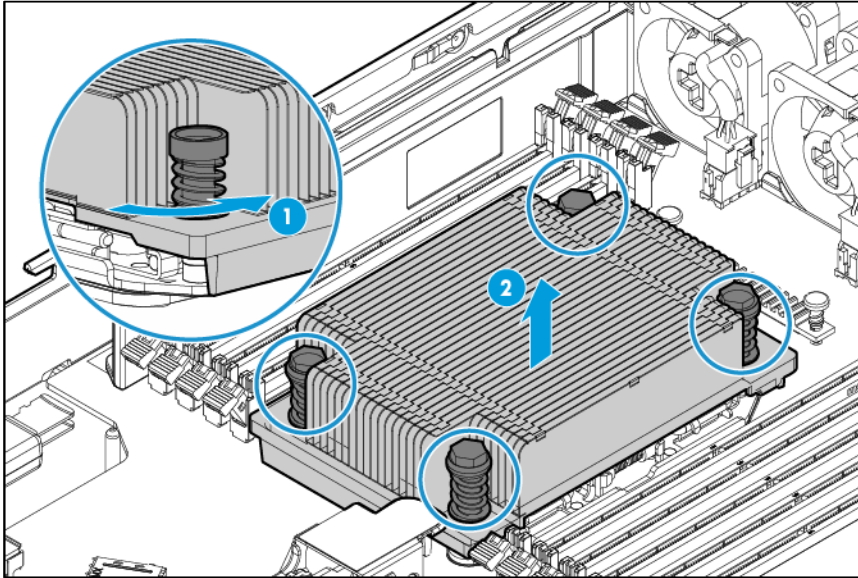


WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

To remove the component:

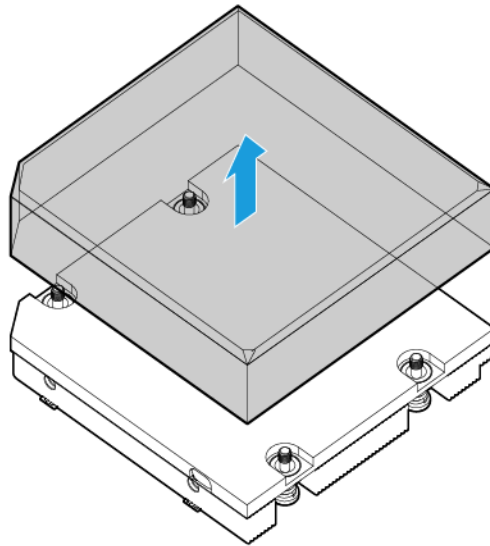
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove the heatsink:
 - a. Loosen one pair of diagonally opposite screws halfway, and then loosen the other pair of screws.
 - b. Completely loosen all screws in the same sequence.

- c. Remove the heatsink from the processor backplate.



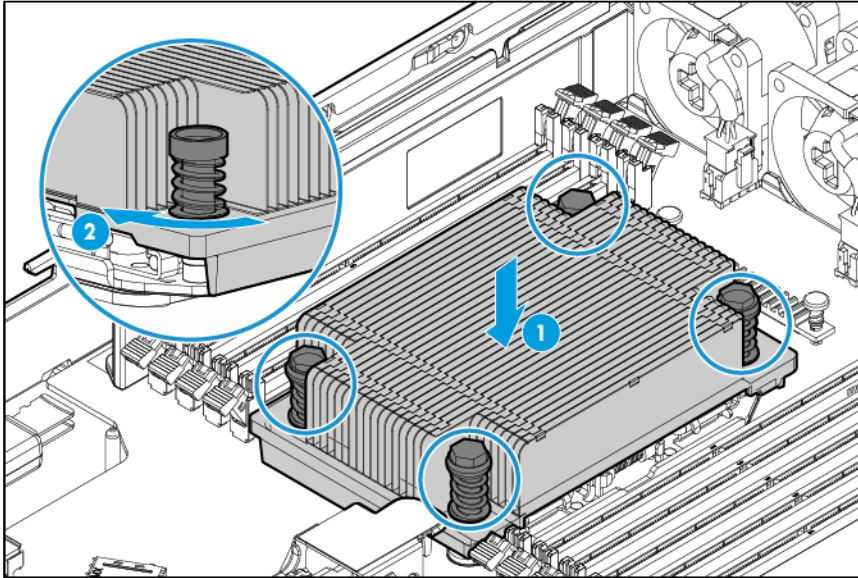
To replace the component:

1. Clean the old thermal grease from the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.
2. Remove the thermal interface protective cover from the heatsink.



3. Install the heatsink:
 - a. Position the heatsink on the processor backplate.
 - b. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.

- c. Finish the installation by completely tightening the screws in the same sequence.





4. Install the access panel.
5. Do one of the following:
 - o Slide the server into the rack.
 - o Install the server into the rack.
6. Connect each power cord to the server.
7. Connect each power cord to the power source.
8. Press the Power On/Standby button.


The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.


Processor


The server supports single-processor and dual-processor operations.

-
-  **WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

 -  **CAUTION:** To avoid damage to the processor and system board, only authorized personnel should attempt to replace or install the processor in this server.

 -  **CAUTION:** To prevent possible server malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.

 -  **CAUTION:** To prevent possible server overheating, always populate processor socket 2 with a processor and a heatsink or a processor socket cover and a heatsink blank.

 -  **IMPORTANT:** If installing a processor with a faster speed, update the system ROM before installing the processor.
-

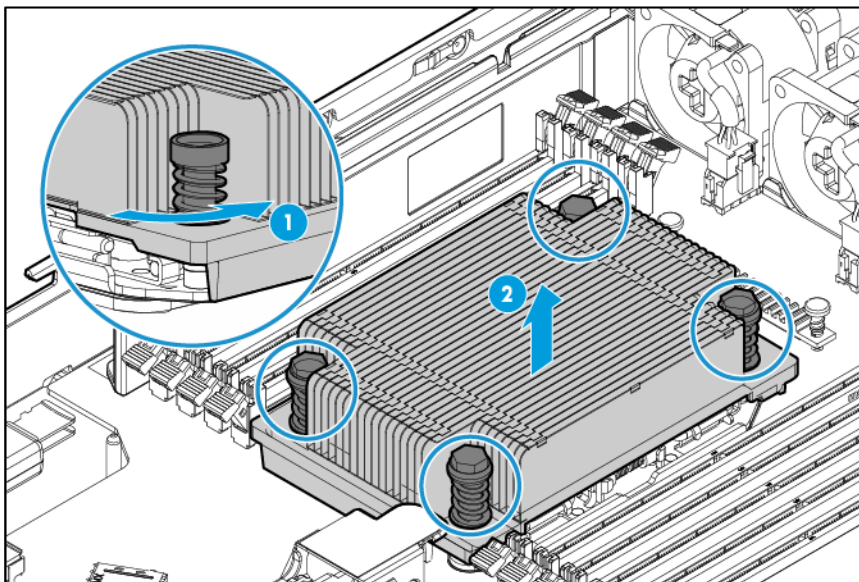


IMPORTANT: Processor socket 1 must be populated at all times or the server does not function.

In a multiprocessor configuration, to optimize system performance, HP recommends balancing the total capacity of the DIMMs across the processors.

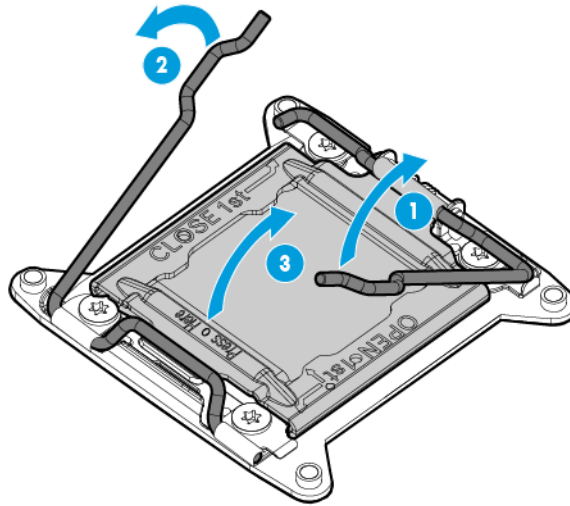
To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove the heatsink:
 - a. Loosen one pair of diagonally opposite screws halfway, and then loosen the other pair of screws.
 - b. Completely loosen all screws in the same sequence.
 - c. Remove the heatsink from the processor backplate.



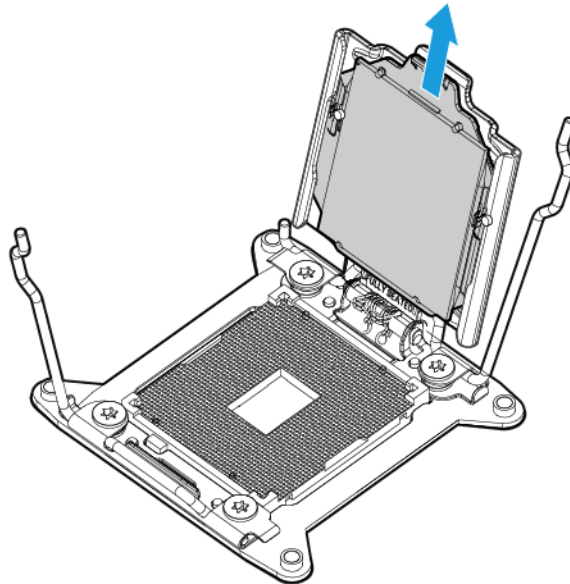
CAUTION: The pins on the processor socket are very fragile. Any damage to them may require replacing the system board.

6. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

7. Remove the processor from the processor retaining bracket.

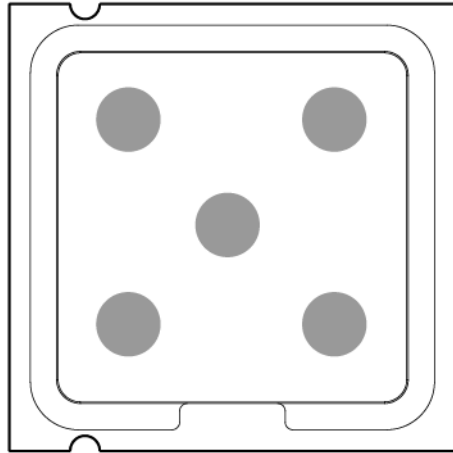


CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

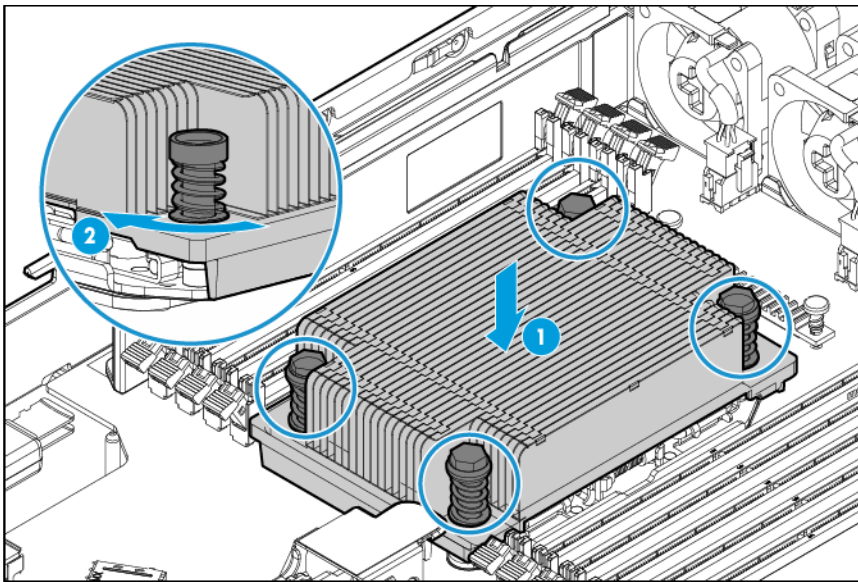
To replace the component:

1. Clean the old thermal grease from the heatsink with the alcohol swab. Allow the alcohol to evaporate before continuing.

2. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.



3. Install the heatsink:
 - a. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.
 - b. Finish the installation by completely tightening the screws in the same sequence.



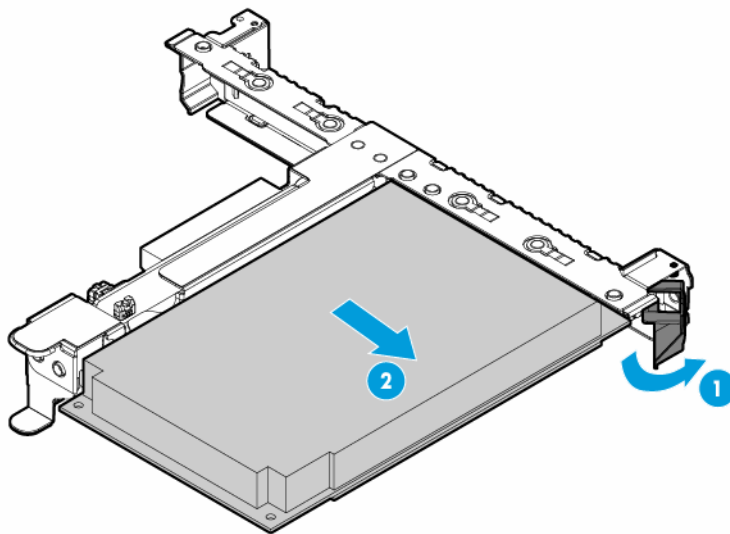
4. Install the access panel.
5. Do one of the following:
 - o Slide the server into the rack.
 - o Install the server into the rack.
6. Connect each power cord to the server.
7. Connect each power cord to the power source.
8. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

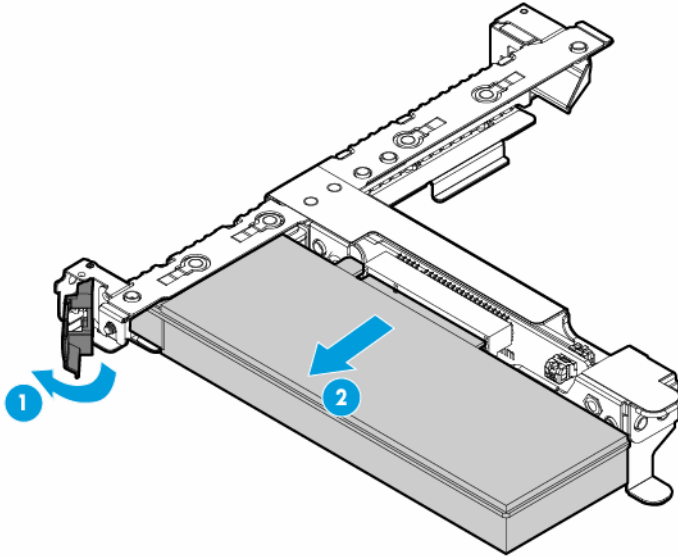
Expansion board

To remove the component:

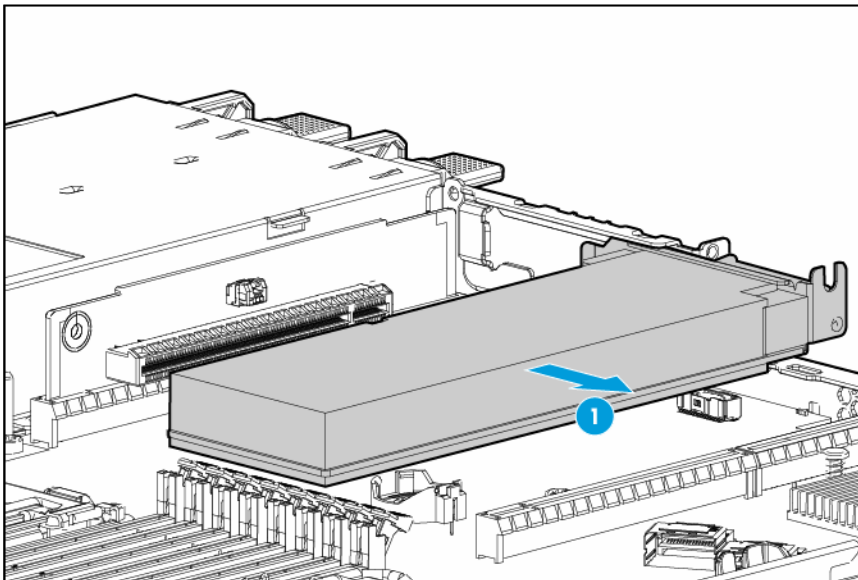
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Disconnect all cables connected to existing expansion boards.
6. Remove the PCI riser cage ("Primary PCIe riser board" on page 49).
7. Remove the expansion board.
 - o Slot 1



- Slot 2



- Slot 3



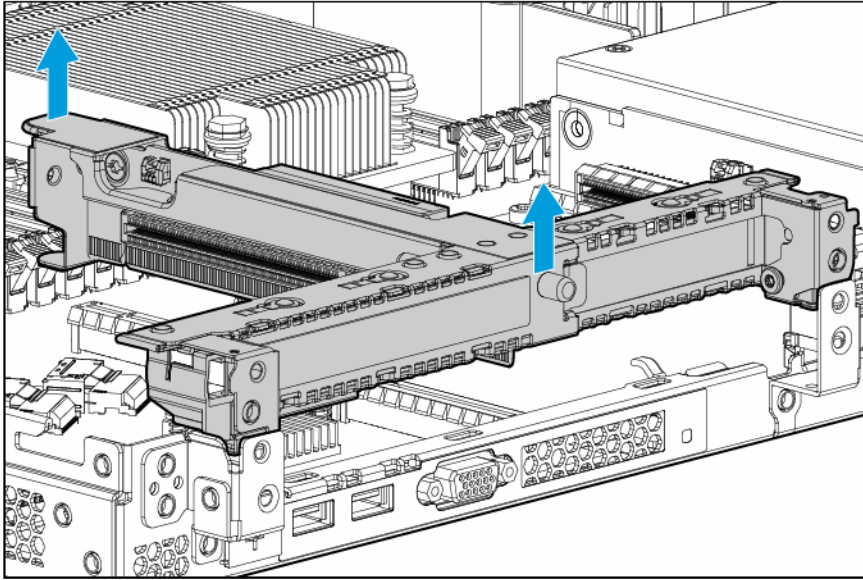
To replace the component, reverse the removal procedure.

Primary PCIe riser board

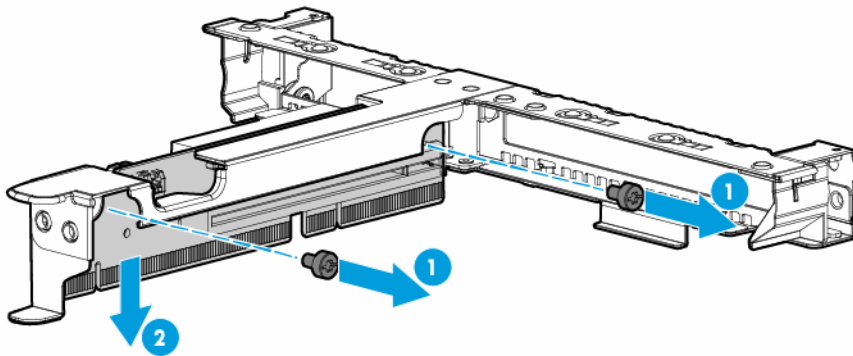
To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - Extend the server from the rack (on page 28).

- Remove the server from the rack (on page 29).
- 4. Remove the access panel ("Access panel" on page 30).
- 5. Disconnect all cables connected to existing expansion boards.
- 6. Remove the PCI riser cage ("Primary PCIe riser board" on page 49).



- 7. Remove any existing expansion board from the riser board.
- 8. Remove the riser board from the cage.



To replace the component, reverse the removal procedure.

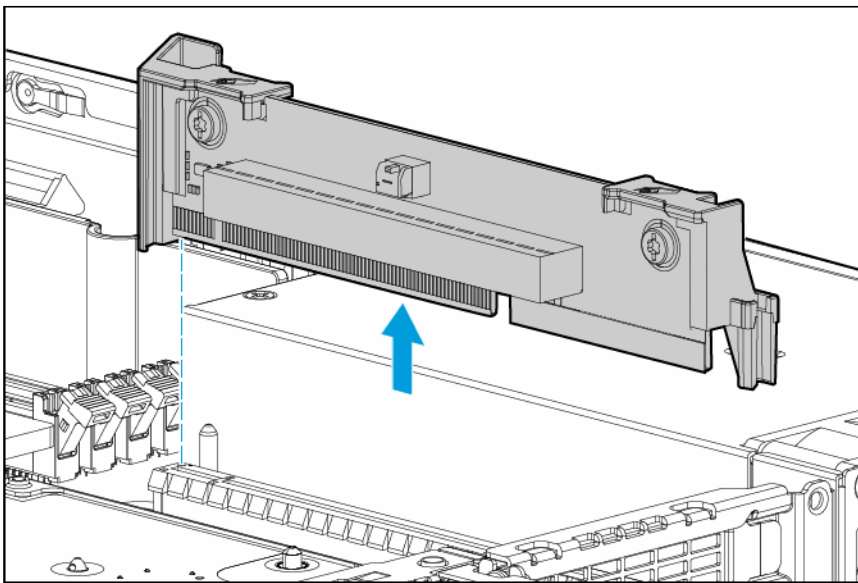
Secondary PCIe riser board



CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all PCI slots have either an expansion slot cover or an expansion board installed.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Disconnect all cables connected to existing expansion boards.
6. Remove all expansion boards.
7. Grasp the plastic ends of the riser board and lift up.



To replace the component, reverse the removal procedure.

System battery

If the server no longer automatically displays the correct date and time, then replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.



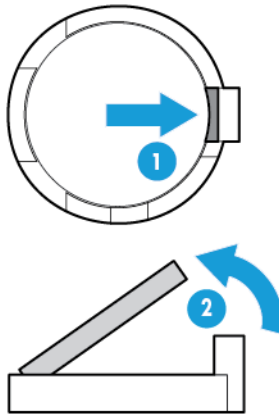
WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. Power down the server (on page 26).

2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove the secondary PCIe riser cage ("Secondary PCIe riser board" on page 50).
6. Locate the battery on the system board ("System board components" on page 76).
7. Remove the battery.



IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, use BIOS/Platform Configuration (RBSU) in the UEFI System Utilities ("HP UEFI System Utilities" on page 65) to reconfigure the system.

To replace the component, reverse the removal procedure.

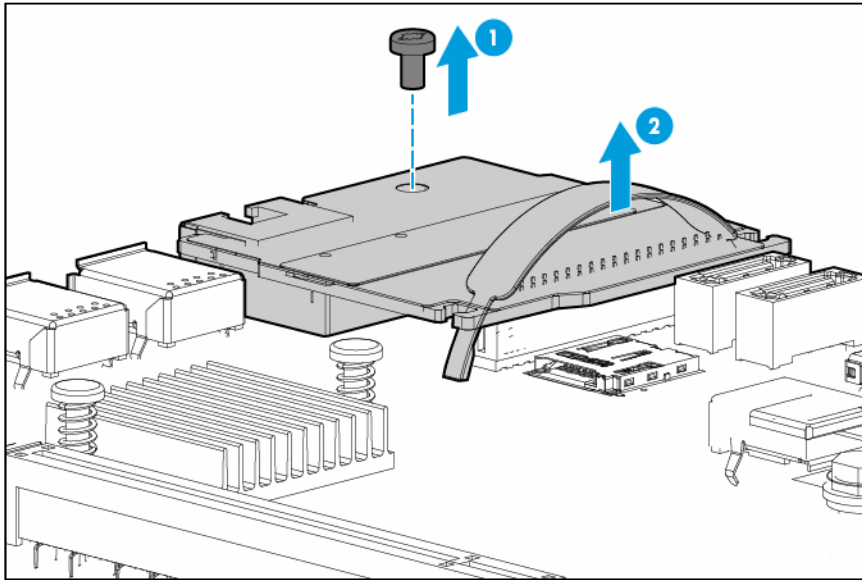
For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Dedicated iLO management module

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).

5. Remove the primary PCI riser cage ("Primary PCIe riser board" on page 49).
6. Remove the dedicated iLO management module.



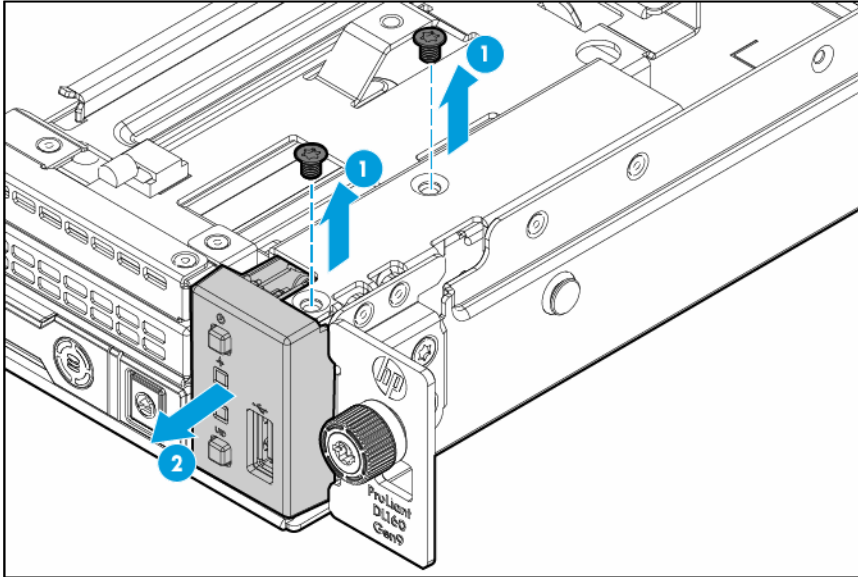
To replace the component, reverse the removal procedure.

Front I/O modules for LFF and SFF drive models

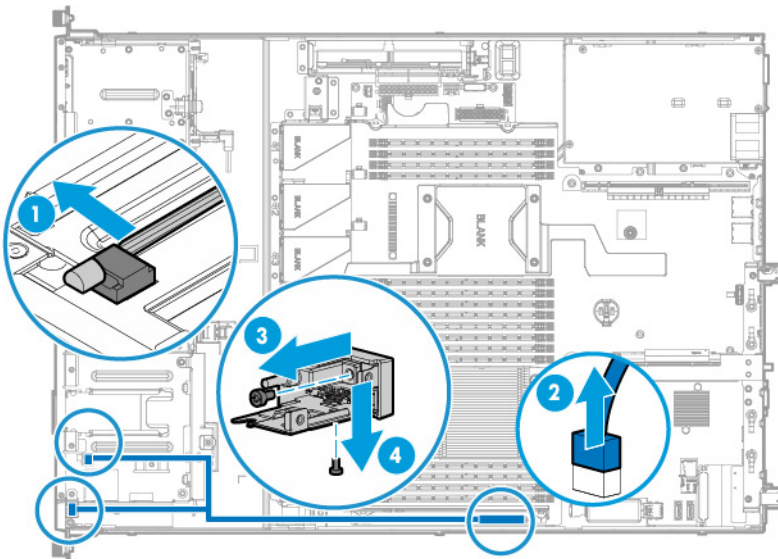
To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Release the front I/O cabling from the server:
 - a. Detach the ambient thermal sensor cable from its clip.
 - b. Release the ambient thermal sensor cable from the front chassis cable clip.
 - c. Disconnect the front I/O module cable.
6. Do one of the following:
 - a. For SFF:

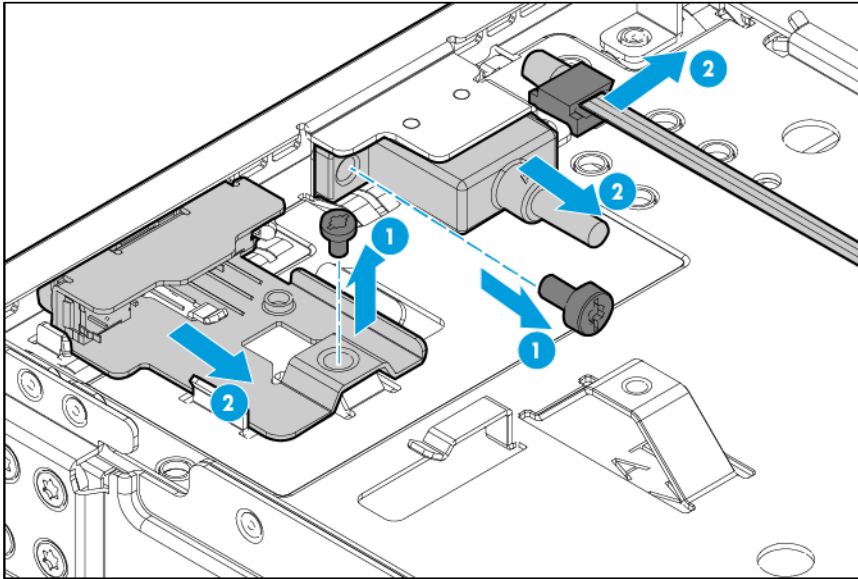
- Remove the front I/O module from the chassis assembly.



- Disconnect the front I/O module cables from the chassis assembly.



- b. For LFF, disconnect the cables for the front I/O module and then remove the front I/O module from the chassis module.



To replace the component, reverse the removal procedure.

System board

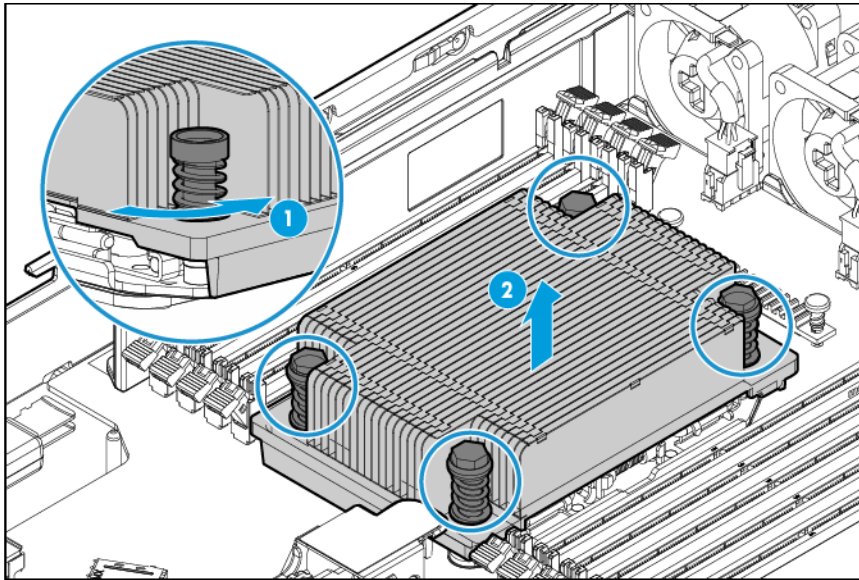


CAUTION: To avoid ESD damage, when removing electrostatic-sensitive components from the failed system board, place the components on a static-dissipating work surface or inside separate antistatic bags.

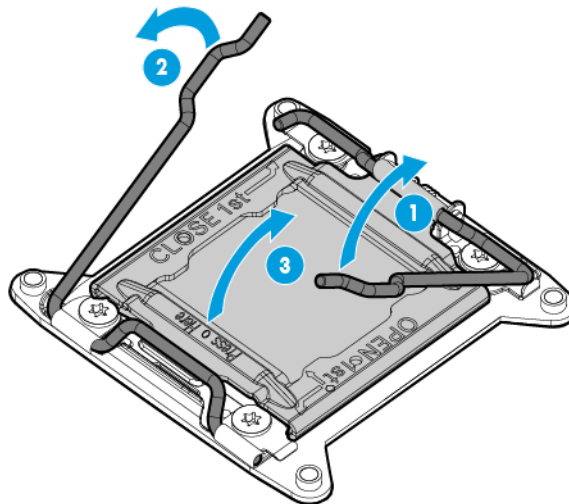
To remove the system board assembly:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Do one of the following:
 - o Extend the server from the rack (on page 28).
 - o Remove the server from the rack (on page 29).
4. Remove the access panel ("Access panel" on page 30).
5. Remove the fans ("Fan and fan blank" on page 38).
6. Remove the fan blanks ("Fan and fan blank" on page 38).
7. Remove the PCI riser cages ("Primary PCIe riser board" on page 49).
8. Remove the dedicated iLO management module.
9. Disconnect all cables connected to the system board.
10. Remove the HP Smart Storage Battery ("HP Smart Storage Battery" on page 34).
11. Remove all DIMMs ("DIMMs" on page 41).
12. If installed, remove the heatsink blank.

13. Remove the heatsink:
 - a. Loosen one pair of diagonally opposite screws halfway, and then loosen the other pair of screws.
 - b. Completely loosen all screws in the same sequence.
 - c. Remove the heatsink from the processor backplate.

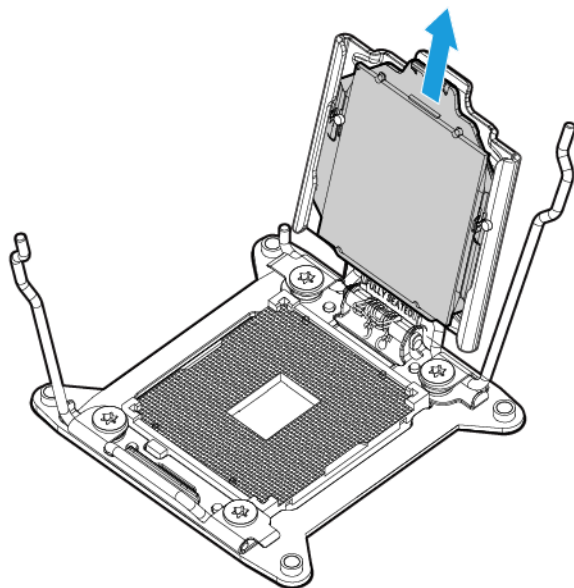


14. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



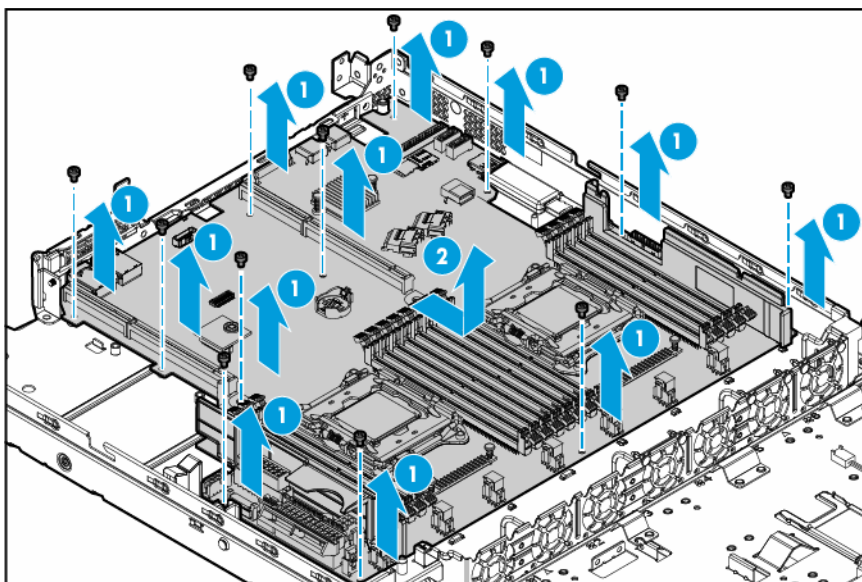
CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

15. Remove the processor from the processor retaining bracket.



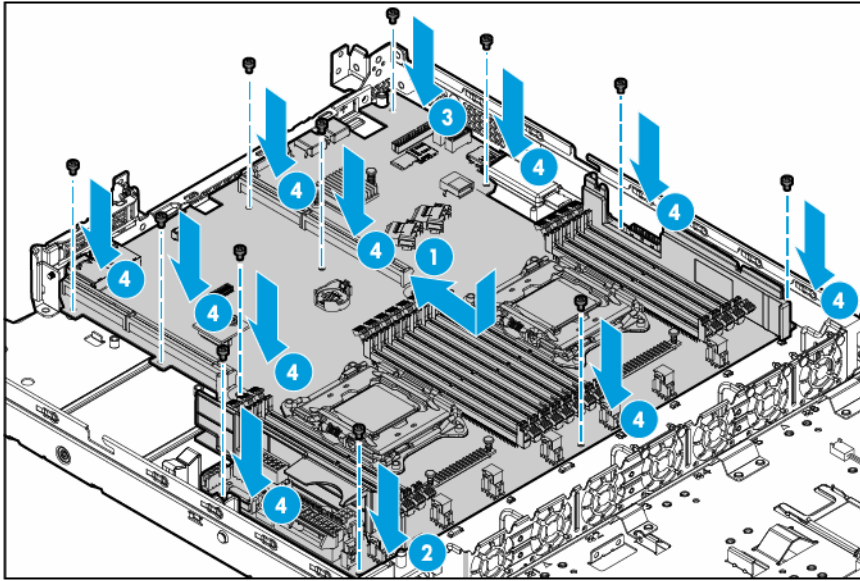
CAUTION: When returning a damaged system board to HP, always install all processor socket covers to prevent damage to the processor sockets and system board.

16. Remove the system board:
 - a. Remove the system board screws.
 - b. Lift the system board out of the chassis.

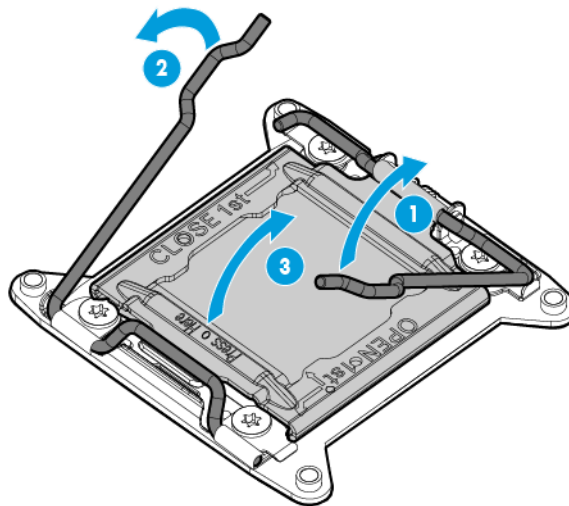


To replace the system board assembly:

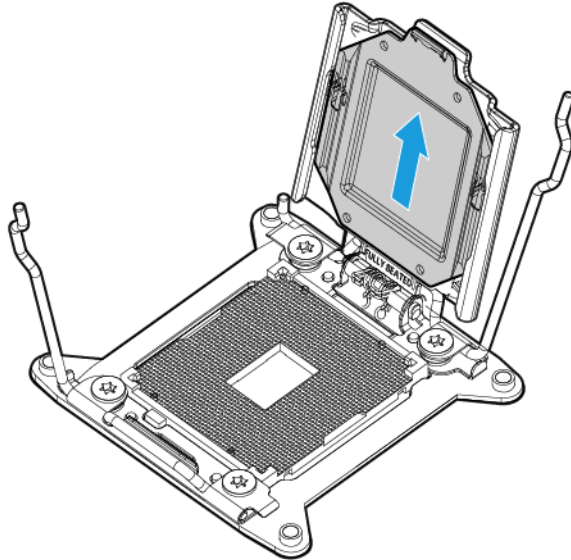
1. Install the system board assembly.



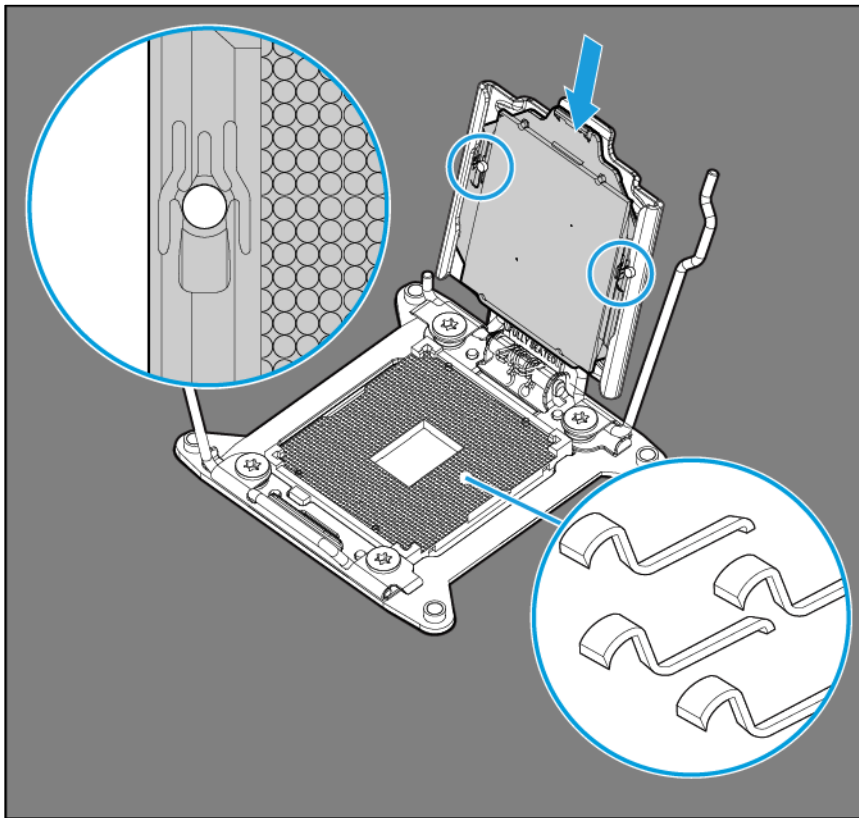
2. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



3. Remove the clear processor socket cover. Retain the processor socket cover for future use.



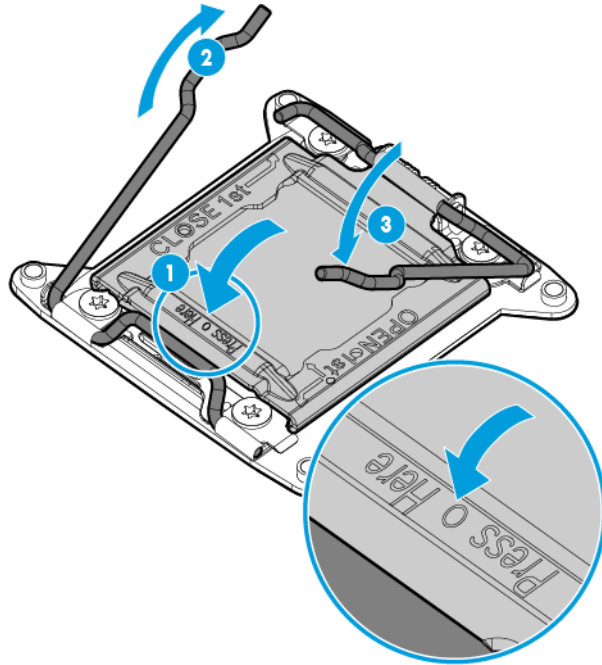
4. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**



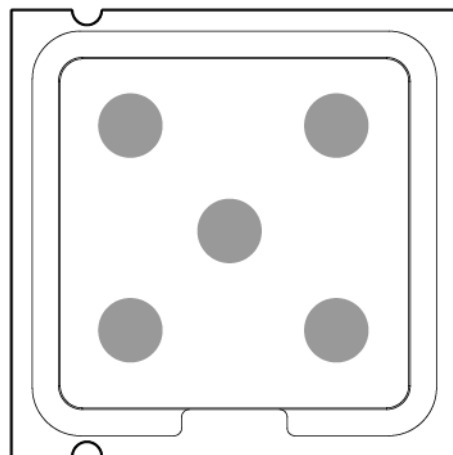
CAUTION: Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

CAUTION: Close and hold down the processor cover socket while closing the processor locking levers. The levers should close without resistance. Forcing the levers closed can damage the processor and socket, requiring system board replacement.

5. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.
6. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.

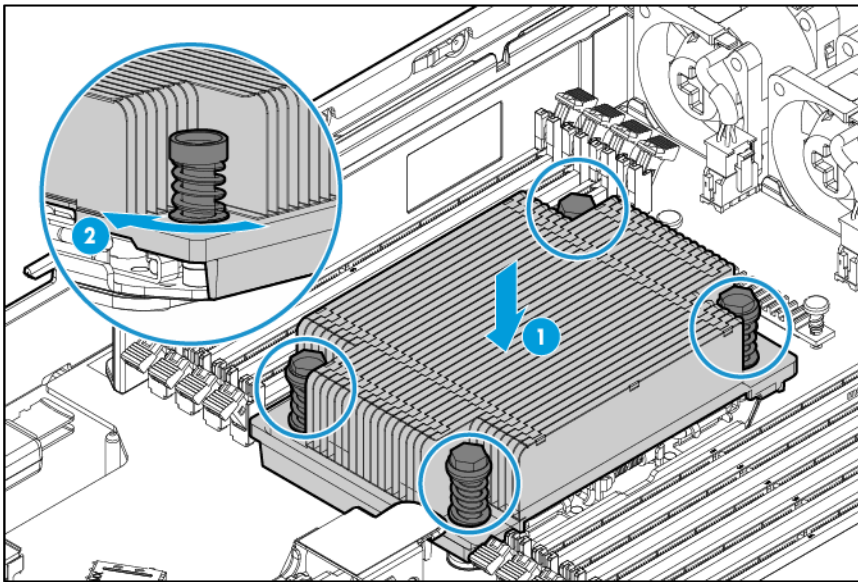


7. Install the processor socket cover onto the processor socket of the failed system board.
8. Clean the old thermal grease from the heatsink and the top of the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.
9. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.



10. Install the heatsink:

- a. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.
- b. Finish the installation by completely tightening the screws in the same sequence.



11. Install the fans.
12. Install all components removed from the failed system board.
13. Connect all cables disconnected from the failed system board.
14. Install the PCI riser cages.
15. Install the access panel.
16. Do one of the following:
 - o Slide the server into the rack.
 - o Install the server into the rack.
17. Connect each power cord to the server.
18. Connect each power cord to the power source.
19. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.



IMPORTANT: Install all components with the same configuration that was used on the failed system board.

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warning appears:
Warning: The serial number should ONLY be modified by qualified service personnel. This value should always match the serial number located on the chassis.
5. Press the **Enter** key to clear the warning.

6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID located on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

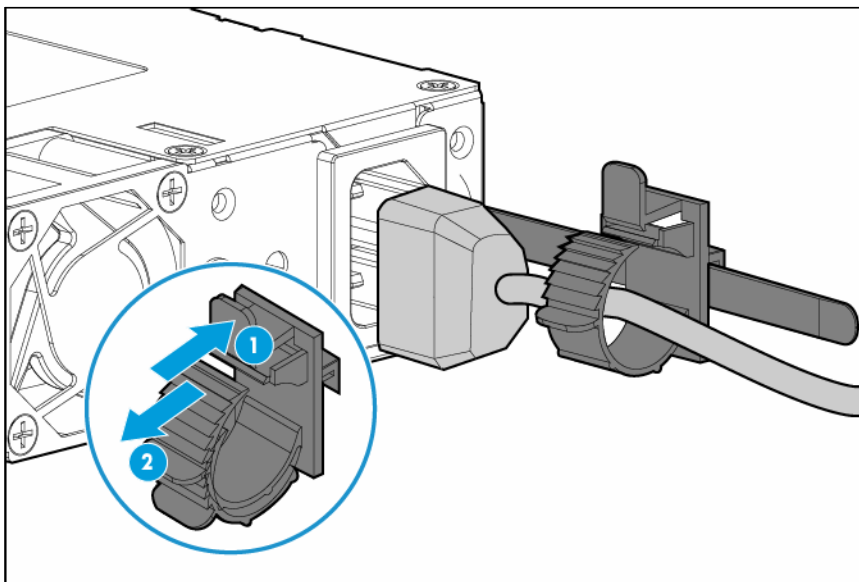
HP 550-W Power Supply

WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

CAUTION: To prevent damage to electrical components, take the appropriate anti-static precautions before beginning any installation, removal, or replacement procedure. Improper grounding can cause electrostatic discharge.

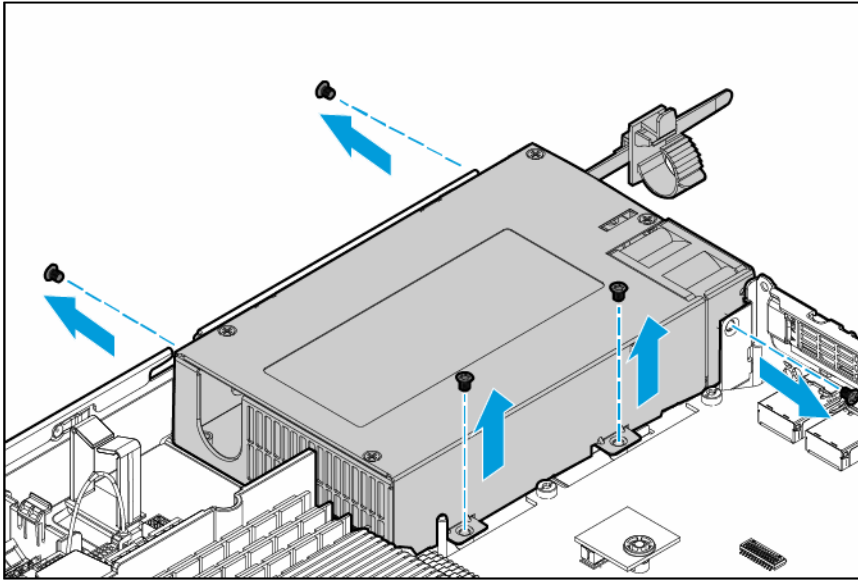
To remove the component:

1. Power down the server (on page 26).
2. Remove the server from the rack. ("[Remove the server from the rack](#)" on page 29)
3. Access the product rear panel.
4. Release the power cord from the strain relief clip.



5. Remove all power:
 - a. Disconnect the power cord from the power source.
 - b. Disconnect the power cord from the server.
6. Remove the server from the rack (on page 29).
7. Remove the access panel ("[Access panel](#)" on page 30).

8. Disconnect all power supply cables from the system board and any associated component (drive backplane, GPU, etc.).
9. Remove the non-hot-plug power supply.



To replace the component, reverse the removal procedure.

HP Trusted Platform Module

The TPM is not a customer-removable part.



CAUTION: Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

If you suspect a TPM board failure, leave the TPM installed and remove the system board. Contact an HP authorized service provider for a replacement system board and TPM board.

Troubleshooting

Troubleshooting resources

The *HP ProLiant Gen9 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/Gen9_TSG_en)
- French (http://www.hp.com/support/Gen9_TSG_fr)
- Spanish (http://www.hp.com/support/Gen9_TSG_es)
- German (http://www.hp.com/support/Gen9_TSG_de)
- Japanese (http://www.hp.com/support/Gen9_TSG_ja)
- Simplified Chinese (http://www.hp.com/support/Gen9_TSG_zh_cn)

The *HP ProLiant Gen9 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/Gen9_EMG_en)
- French (http://www.hp.com/support/Gen9_EMG_fr)
- Spanish (http://www.hp.com/support/Gen9_EMG_es)
- German (http://www.hp.com/support/Gen9_EMG_de)
- Japanese (http://www.hp.com/support/Gen9_EMG_ja)
- Simplified Chinese (http://www.hp.com/support/Gen9_EMG_zh_cn)

Diagnostic tools

HP UEFI System Utilities

The HP UEFI System Utilities is embedded in the system ROM. The UEFI System Utilities enable you to perform a wide range of configuration activities, including:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller
- Configuring memory options
- Selecting a language
- Launching other pre-boot environments such as the Embedded UEFI Shell and Intelligent Provisioning

For more information on the HP UEFI System Utilities, see the *HP UEFI System Utilities User Guide for HP ProLiant Gen9 Servers* on the HP website (<http://www.hp.com/go/ProLiantUEFI/docs>).

Scan the QR code located at the bottom of the screen to access mobile-ready online help for the UEFI System Utilities and UEFI Shell. For on-screen help, press **F1**.

Using HP UEFI System Utilities

To use the System Utilities, use the following keys.

Action	Key
Access System Utilities	F9 during server POST
Navigate menus	Up and Down arrows
Select items	Enter
Save selections	F10
Access Help for a highlighted configuration option*	F1

*Scan the QR code on the screen to access online help for the UEFI System Utilities and UEFI Shell.

Default configuration settings are applied to the server at one of the following times:

- Upon the first system power-up
- After defaults have been restored

Default configuration settings are sufficient for typical server operations; however, you can modify configuration settings as needed. The system prompts you for access to the System Utilities each time the system is powered up.

Flexible boot control

This feature enables you to do the following:

- Add Boot Options
 - Browse all FAT16 and FAT32 file systems.
 - Select an X64 UEFI application with an .EFI extension to add as a new UEFI boot option, such as an OS boot loader or other UEFI application.

The new boot option is appended to the boot order list. When you select a file, you are prompted to enter the boot option description (which is then displayed in the Boot menu), as well as any optional data to be passed to an .EFI application.
- Boot to System Utilities

Toward the end of the boot process, the boot options screen appears. This screen is visible for several seconds before the system attempts to boot from a supported boot device. During this time, you can access the System Utilities by pressing the **F9** key.
- Choose between supported modes: Legacy BIOS Boot Mode or UEFI Boot Mode



IMPORTANT: If the default boot mode settings are different than the user defined settings, the system may not boot the OS installation if the defaults are restored. To avoid this issue, use the User Defined Defaults feature in UEFI System Utilities to override the factory default settings.

For more information, see the *HP UEFI System Utilities User Guide for HP ProLiant Gen9 Servers* on the HP website (<http://www.hp.com/go/ProLiantUEFI/docs>).

Restoring and customizing configuration settings

You can reset all configuration settings to the factory default settings, or you can restore system default configuration settings, which are used instead of the factory default settings.

You can also configure default settings as necessary, and then save the configuration as the custom default configuration. When the system loads the default settings, it uses the custom default settings instead of the factory defaults.

Secure Boot configuration

Secure Boot is integrated in the UEFI specification on which the HP implementation of UEFI is based. Secure Boot is completely implemented in the BIOS and does not require special hardware. It ensures that each component launched during the boot process is digitally signed and that the signature is validated against a set of trusted certificates embedded in the UEFI BIOS. Secure Boot validates the software identity of the following components in the boot process:

- UEFI drivers loaded from PCIe cards
- UEFI drivers loaded from mass storage devices
- Pre-boot UEFI shell applications
- OS UEFI boot loaders

Once enabled, only firmware components and operating systems with boot loaders that have an appropriate digital signature can execute during the boot process. Only operating systems that support Secure Boot and have an EFI boot loader signed with one of the authorized keys can boot when Secure Boot is enabled. For

more information about supported operating systems, see the *HP UEFI System Utilities and Shell Release Notes* on the HP website (<http://www.hp.com/go/ProLiantUEFI/docs>).

A physically present user can customize the certificates embedded in the UEFI BIOS by adding/removing their own certificates.

Embedded UEFI shell

The system BIOS in all HP ProLiant Gen9 servers includes an Embedded UEFI Shell in the ROM. The UEFI Shell environment provides an API, a command line prompt, and a set of CLIs that allow scripting, file manipulation, and system information. These features enhance the capabilities of the UEFI System Utilities.

For more information, see the following documents:

- *HP UEFI Shell User Guide for HP ProLiant Gen9 Servers* on the HP website (<http://www.hp.com/go/ProLiantUEFI/docs>)
- *UEFI Shell Specification* on the UEFI website (<http://www.uefi.org/specifications>)

Embedded Diagnostics option

The system BIOS in all HP ProLiant Gen9 servers includes an Embedded Diagnostics option in the ROM. The Embedded Diagnostics option can run comprehensive diagnostics of the server hardware, including processors, memory, drives, and other server components.

For more information on the Embedded Diagnostics option, see the *HP UEFI System Utilities User Guide for HP ProLiant Gen9 Servers* on the HP website (<http://www.hp.com/go/ProLiantUEFI/docs>).

HP RESTful API support for UEFI

HP ProLiant Gen9 servers include support for a UEFI compliant System BIOS, along with UEFI System Utilities and Embedded UEFI Shell pre-boot environments. HP ProLiant Gen9 servers also support configuring the UEFI BIOS settings using the HP RESTful API, a management interface that server management tools can use to perform configuration, inventory, and monitoring of an HP ProLiant server. A REST client uses HTTPS operations to configure supported server settings, such as UEFI BIOS settings.

For more information about the HP RESTful API and the HP RESTful Interface Tool, see the HP website (<http://www.hp.com/support/restfulinterface/docs>).

Re-entering the server serial number and product ID

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access UEFI System Utilities.
2. Select the **System Configuration > BIOS/Platform Configuration (RBSU) > Advanced Options > Advanced System ROM Options > Serial Number**, and then press the **Enter** key.
3. Enter the serial number and press the **Enter** key. The following message appears:
The serial number should only be modified by qualified service personnel.
This value should always match the serial number located on the chassis.
4. Press the **Enter** key to clear the warning.
5. Enter the serial number and press the **Enter** key.
6. Select **Product ID**. The following warning appears:

Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID located on the chassis.

7. Enter the product ID and press the **Enter** key.
8. Press the **F10** key to confirm exiting System Utilities. The server automatically reboots.

HP ProLiant Pre-boot Health Summary

If the server does not power on, you can use Dedicated iLO management to display diagnostic information on an external monitor. This feature is supported on servers that support external video and have a UID button. When power is available to the server but the server is not powered on, iLO runs on auxiliary power and can take control of the server video adapter to display the HP ProLiant Pre-boot Health Summary.

For additional information, see the *HP iLO 4 User Guide* on the HP website (<http://www.hp.com/go/ilo>) or the *HP ProLiant Gen9 Troubleshooting Guide, Volume I: Troubleshooting*.

The *HP ProLiant Gen9 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

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- Spanish (http://www.hp.com/support/Gen9_TSG_es)
- German (http://www.hp.com/support/Gen9_TSG_de)
- Japanese (http://www.hp.com/support/Gen9_TSG_ja)
- Simplified Chinese (http://www.hp.com/support/Gen9_TSG_zh_cn)

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, boot the server using Intelligent Provisioning.

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft Windows and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, see the HP website (<http://www.hp.com/servers/diags>). HP Insight Diagnostics Online Edition is also available in the SPP.

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 68) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that are supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every Intelligent Provisioning-assisted HP Insight Diagnostics installation, or it can be installed through the SPP.

Active Health System

HP Active Health System provides the following features:

- Combined diagnostics tools/scanners
- Always on, continuous monitoring for increased stability and shorter downtimes
- Rich configuration history
- Health and service alerts
- Easy export and upload to Service and Support

The HP Active Health System monitors and records changes in the server hardware and system configuration. The Active Health System assists in diagnosing problems and delivering rapid resolution if server failures occur.

The Active Health System collects the following types of data:

- Server model
- Serial number
- Processor model and speed
- Storage capacity and speed
- Memory capacity and speed
- Firmware/BIOS

HP Active Health System does not collect information about Active Health System users' operations, finances, customers, employees, partners, or data center, such as IP addresses, host names, user names, and passwords. HP Active Health System does not parse or change operating system data from third-party error event log activities, such as content created or passed through by the operating system.

The data that is collected is managed according to the HP Data Privacy policy. For more information see the HP website (<http://www.hp.com/go/privacy>).

The Active Health System, in conjunction with the system monitoring provided by Agentless Management or SNMP Pass-thru, provides continuous monitoring of hardware and configuration changes, system status, and service alerts for various server components.

The Agentless Management Service is available in the SPP, which can be downloaded from the HP website (<http://www.hp.com/go/spp/download>). The Active Health System log can be downloaded manually from Dedicated iLO management or HP Intelligent Provisioning and sent to HP.

For more information, see the following documents:

- *HP iLO User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>)
- *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/intelligentprovisioning/docs>)

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within HP UEFI System Utilities (on page [65](#))
- From within the Embedded UEFI shell (on page [67](#))
- From within operating system-specific IML viewers:
 - For Windows: IML Viewer
 - For Linux: IML Viewer Application
- From within the Dedicated iLO management web interface
- From within HP Insight Diagnostics (on page [68](#))

USB support

HP provides standard USB 2.0 support, standard USB 3.0 support, and legacy USB support. Standard support is provided by the OS through the appropriate USB device drivers.

Before the OS loads, HP provides support for USB 2.0 devices through legacy USB support, which is enabled by default in the system ROM. USB 3.0 ports are not functional before the OS loads. The native OS provides USB 3.0 support through appropriate xHCI drivers.

Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST (system boot)
- UEFI System Utilities
- Pre-boot UEFI shell
- DOS
- Operating environments which do not provide native USB support

External USB functionality

HP provides external USB support to enable local connection of USB devices for server administration, configuration, and diagnostic procedures.

For additional security, external USB functionality can be disabled through USB options in UEFI System Utilities.

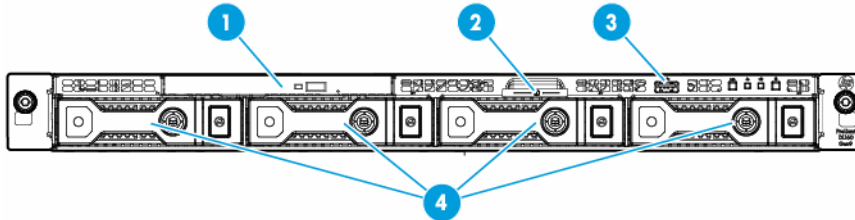
Internal USB functionality

An internal USB connector is available for use with security key devices and USB drive keys. This solution provides for use of a permanent USB key installed in the internal connector, avoiding issues of clearance on the front of the rack and physical access to secure data.

Component identification

Front panel components

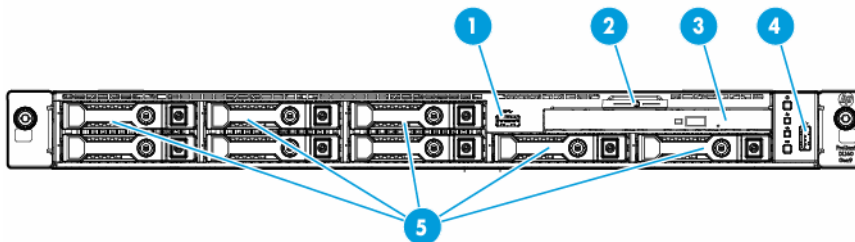
- Four-bay LFF drive model



Item	Description
1	Optical drive (optional)
2	Serial number pull tab*
3	USB 2.0 connector
4	LFF drives (8.89 cm, 3.5 in)

*The serial number/iLO information pull tab is double-sided. The top side shows the server serial number and the customer asset tag label. The reverse side shows the default iLO account information and QR code linking to product documentation resources. The serial number/iLO information is printed on labels attached to the chassis.

- Eight-bay SFF drive model

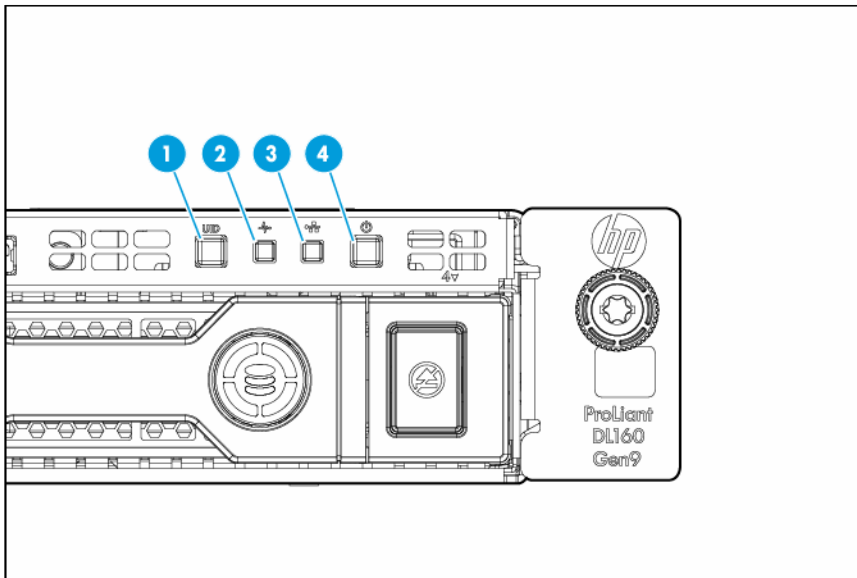


Item	Description
1	Front USB 3.0 connector (optional)
2	Serial number pull tab*
3	Optical drive (optional)
4	USB 2.0 connector
5	SFF drives (6.35 cm, 2.5 in)

*The serial number/iLO information pull tab is double-sided. The top side shows the server serial number and the customer asset tag label. The reverse side shows the default iLO account information and QR code linking to product documentation resources. The serial number/iLO information is printed on labels attached to the chassis.

Front panel LEDs and buttons

- Four-bay LFF drive model



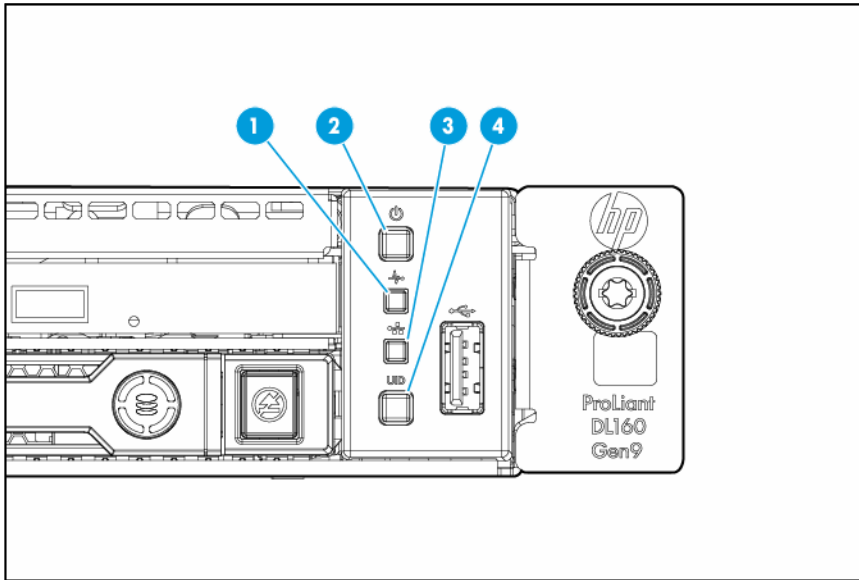
Item	Description	Status
1	UID button/LED*	Solid blue = Activated Flashing blue: <ul style="list-style-type: none"> • 1 Hz/cycle per sec = Remote management or firmware upgrade in progress • 4 Hz/cycle per sec = iLO manual reboot sequence initiated • 8 Hz/cycle per sec = iLO manual reboot sequence in progress Off = Deactivated
2	Health LED*	Solid green = Normal Flashing green (1 Hz/cycle per sec) = iLO is rebooting. Flashing amber = System degraded** Flashing red (1 Hz/cycle per sec) = System critical**
3	NIC status LED*	Solid green = Link to network Flashing green (1 Hz/cycle per sec) = Network active Off = No network activity
4	Power On/Standby button and system power LED*	Solid green = System on Flashing green (1 Hz/cycle per sec) = Performing power on sequence Solid amber = System in standby Off = No power present†

*When all four LEDs described in this table flash simultaneously, a power fault has occurred. For more information, see "Power fault LEDs (on page 73)."

**If the health LED indicates a degraded or critical state, review the system IML or use iLO to review the system health status.

†Facility power is not present, power cord is not attached, no power supplies are installed, power supply failure has occurred, or the power button cable is disconnected.

- Eight-bay SFF drive model



Item	Description	Status
1	Health LED*	Solid green = Normal Flashing green (1 Hz/cycle per sec) = iLO is rebooting. Flashing amber = System degraded** Flashing red (1 Hz/cycle per sec) = System critical**
2	Power On/Standby button and system power LED*	Solid green = System on Flashing green (1 Hz/cycle per sec) = Performing power on sequence Solid amber = System in standby Off = No power present†
3	NIC status LED*	Solid green = Link to network Flashing green (1 Hz/cycle per sec) = Network active Off = No network activity
4	UID button/LED*	Solid blue = Activated Flashing blue: <ul style="list-style-type: none"> • 1 Hz/cycle per sec = Remote management or firmware upgrade in progress • 4 Hz/cycle per sec = iLO manual reboot sequence initiated • 8 Hz/cycle per sec = iLO manual reboot sequence in progress Off = Deactivated

*When all four LEDs described in this table flash simultaneously, a power fault has occurred. For more information, see "Power fault LEDs (on page 73)."

**If the health LED indicates a degraded or critical state, review the system IML or use iLO to review the system health status.

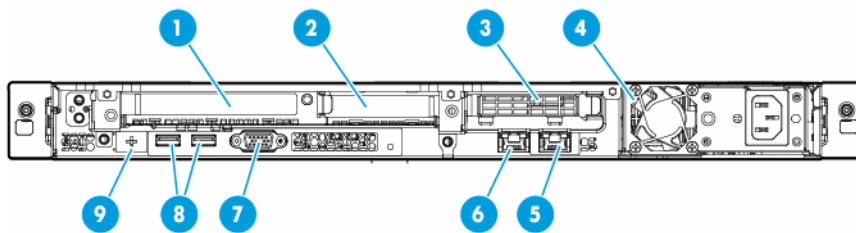
†Facility power is not present, power cord is not attached, no power supplies are installed, power supply failure has occurred, or the power button cable is disconnected.

Power fault LEDs

The following table provides a list of power fault LEDs, and the subsystems that are affected. Not all power faults are used by all servers.

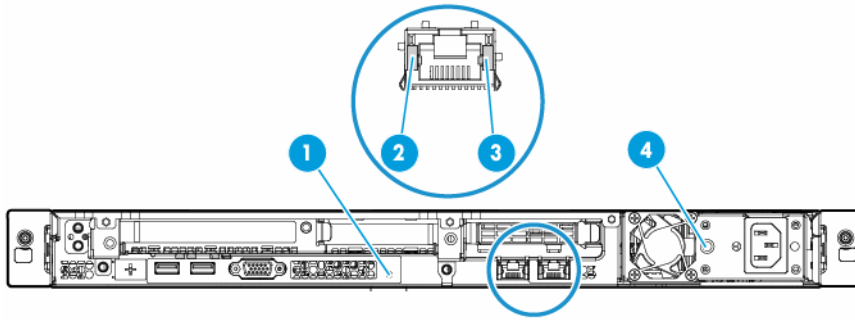
Subsystem	LED behavior
System board	1 flash
Processor	2 flashes
Memory	3 flashes
Riser board PCIe slots	4 flashes
FlexibleLOM	5 flashes
Removable HP Flexible Smart Array controller/Smart SAS HBA controller	6 flashes
System board PCIe slots	7 flashes
Power backplane or storage backplane	8 flashes
Power supply	9 flashes

Rear panel components



Item	Description
1	Slot 1 PCIe3 x16 (16, 8, 4, 1)
2	Slot 2 PCIe3 x8 (8, 4, 1)
3	Slot 3 PCIe3 x16 (16, 8, 4, 1)
4	Power supply
5	NIC connector 2
6	NIC connector 1
7	Video connector
8	USB 3.0 connectors
9	Dedicated iLO connector (optional)

Rear panel LEDs

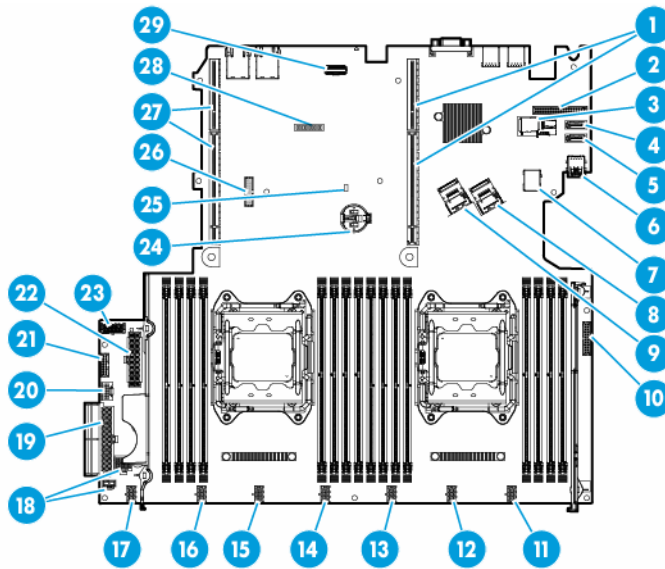


Item	Description	Status
1	UID LED	Solid blue = Activated Flashing blue: <ul style="list-style-type: none"> • 1 Hz/cycle per sec = Remote management or firmware upgrade in progress • 4 Hz/cycle per sec = iLO manual reboot sequence initiated • 8 Hz/cycle per sec = iLO manual reboot sequence in progress Off = Deactivated
2	NIC link LED	Green = Network link Off = No network link
3	NIC activity LED	Solid green = Link to network Flashing green = Network active Off = No network activity
4	Power supply LED	Solid green = Normal Off = One or more of the following conditions exists: <ul style="list-style-type: none"> • Power is unavailable • Power supply failed • Power supply is in standby mode • Power supply error

PCIe riser board slot definitions

Slot number	Riser board option	Type	Length	Height	Connector link width	Negotiable link width
1	—	PCIe3	Half	Full	x16	x16
2	—	PCIe3	Low-profile	Low-profile	x8	x8
3	Processor 2 riser option	PCIe3	Low-profile	Low-profile	x16	x16

System board components



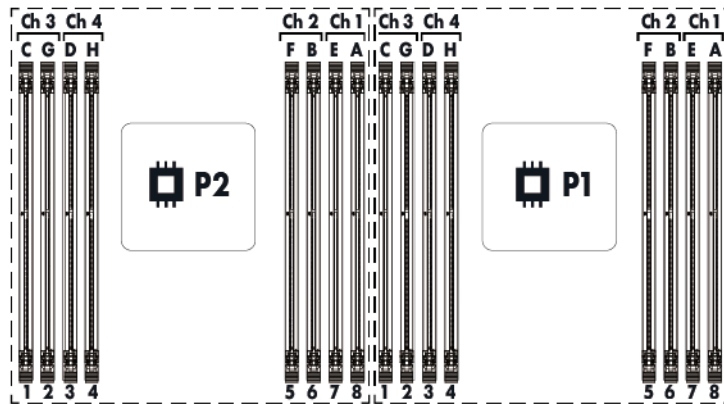
Item	Description
1	Primary PCIe riser board connectors*
2	Dedicated iLO module connector
3	microSD slot
4	SATA connector (port 5)
5	SATA optical drive connector (port 4)
6	Internal USB 3.0 connector (for USB flash devices)
7	8SFF front USB 3.0 connector
8	Mini-SAS connector 1
9	Mini-SAS connector 2
10	Front I/O connector
11	Fan connector 7
12	Fan connector 6
13	Fan connector 5
14	Fan connector 4
15	Fan connector 3
16	Fan connector 2
17	Fan connector 1
18	Reserved
19	24-pin power supply connector
20	HP Smart Storage Battery connector
21	Power supply sideband signal connector
22	20-pin drive power connector
23	10-pin RPS connector
24	System battery
25	NMI header
26	TPM connector
27	Secondary PCIe riser board connectors*

Item	Description
28	System maintenance switch
29	FlexibleLOM sideband signal connector

* For more information on the riser board slots supported by the onboard PCI riser connectors, see "PCIe riser board slot definitions (on page 75)."

DIMM slot locations

DIMM slots are numbered sequentially (1 through 8) for each processor. The supported AMP modes use the letter assignments for population guidelines.



System maintenance switch

Position	Default	Function
S1	Off	Off = iLO security is enabled. On = iLO security is disabled.
S2	Off	Off = System configuration can be changed. On = System configuration is locked.
S3	Off	Reserved
S4	Off	Reserved
S5	Off	Off = Power-on password is enabled. On = Power-on password is disabled.
S6	Off	Off = No function. On = ROM reads system configuration as invalid.
S7	Off	Off = Set default boot mode to UEFI. On = Set default boot mode to legacy.
S8	—	Reserved
S9	—	Reserved
S10	—	Reserved

Position	Default	Function
S11	—	Reserved
S12	—	Reserved

To access the redundant ROM, set S1, S5, and S6 to on.

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.

⚠ CAUTION: Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

NMI functionality

An NMI crash dump creates a crash dump log before resetting a system which is not responding.

Crash dump log analysis is an essential part of diagnosing reliability problems, such as failures of operating systems, device drivers, and applications. Many crashes freeze a system, and the only available action for administrators is to restart the system. Resetting the system erases any information which could support problem analysis, but the NMI feature preserves that information by performing a memory dump before a system reset.

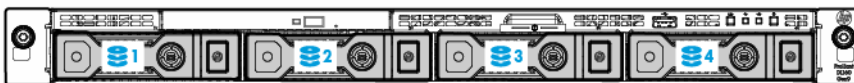
To force the system to invoke the NMI handler and generate a crash dump log, do one of the following:

- Use the iLO Virtual NMI feature.
- Short the NMI header ("System board components" on page 76).

For more information, see the HP website (<http://www.hp.com/support/NMI>).

Drive numbering

- Four-bay LFF drive model



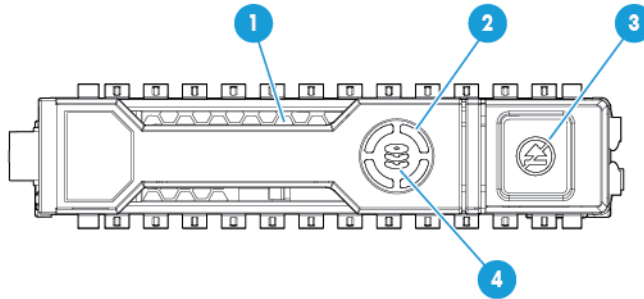
- Eight-bay SFF drive model



HP SmartDrive LED definitions

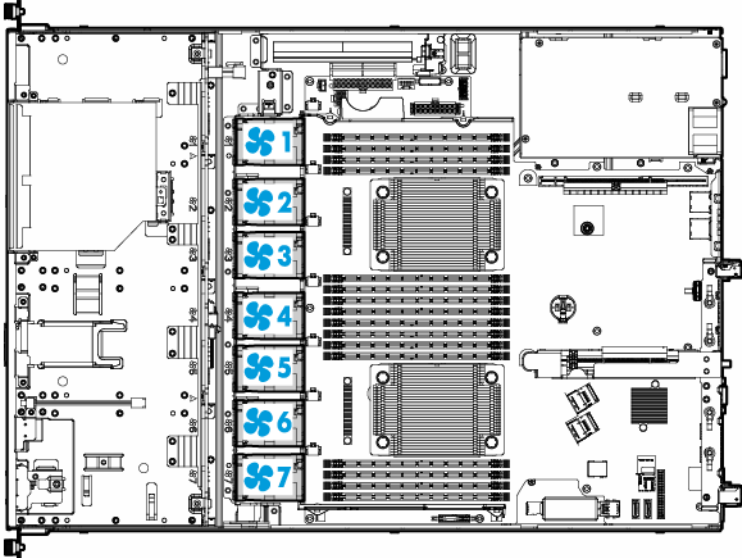
HP SmartDrives are the latest HP drive technology, and they are supported beginning with ProLiant Gen8 servers and server blades. The HP SmartDrive is not supported on earlier generation servers and server blades. Identify an HP SmartDrive by its carrier, shown in the following illustration.

When a drive is configured as a part of an array and connected to a powered-up controller, the drive LEDs indicate the condition of the drive.



Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, strip size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

Fan locations



Cabling

Cabling overview

This section provides guidelines that help you make informed decisions about cabling the server and hardware options to optimize performance.

For information on cabling peripheral components, refer to the white paper on high-density deployment at the HP website (<http://www.hp.com/products/servers/platforms>).

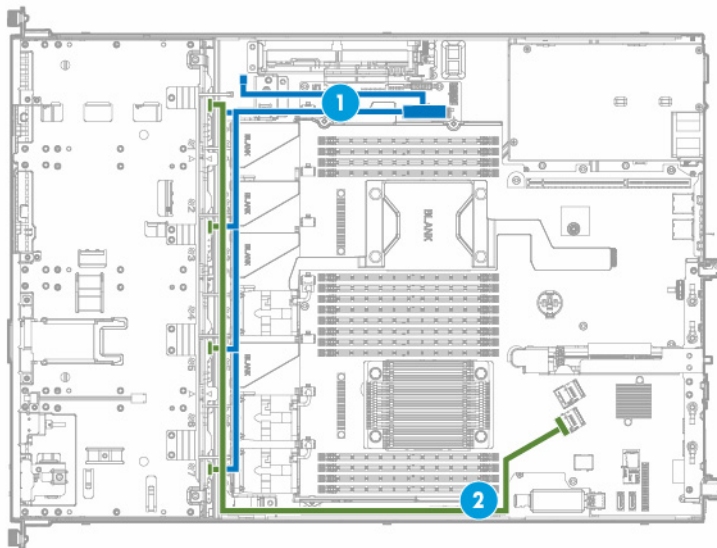
CAUTION: When routing cables, always be sure that the cables are not in a position where they can be pinched or crimped.

Storage cabling

Depending on the controller option installed, the actual storage controller connectors might look different from what is shown in this section.

Four-bay LFF non-hot-plug drive cabling

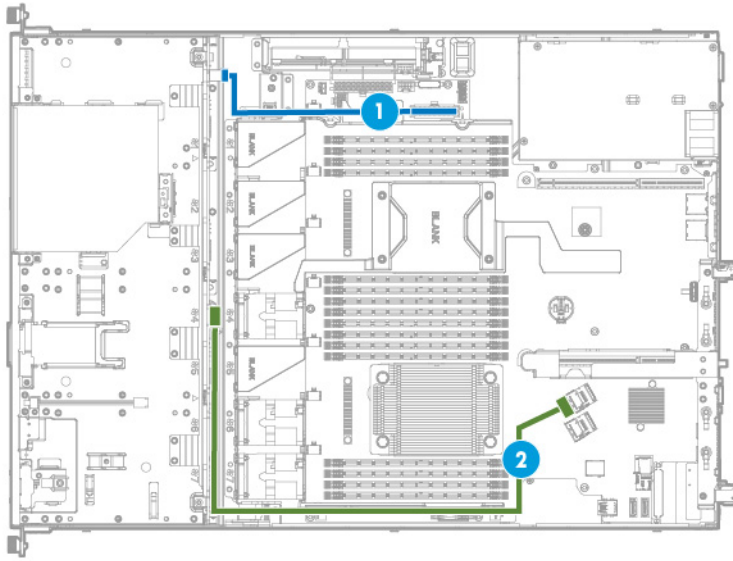
- Four-bay LFF non-hot-plug drive cabling to the system board



Item	Description
1	Drive power cable
2	Mini-SAS cable

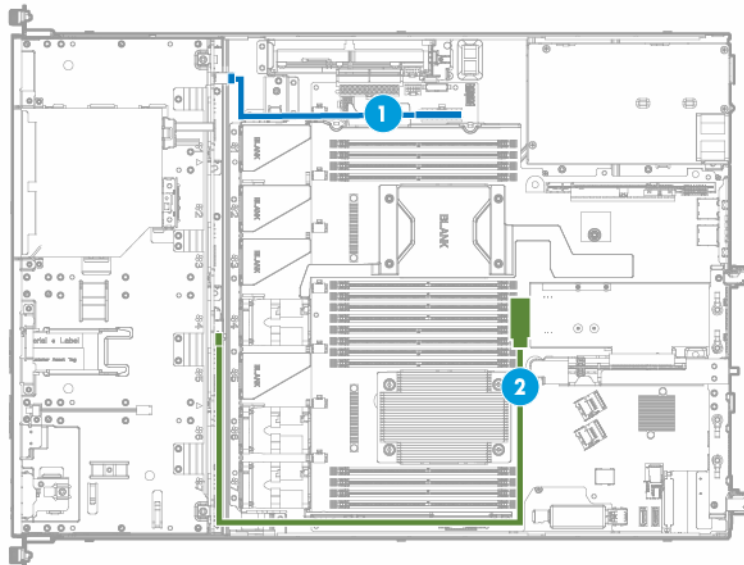
Four-bay LFF hot-plug drive cabling

- Four-bay LFF drive cage connected to the system board



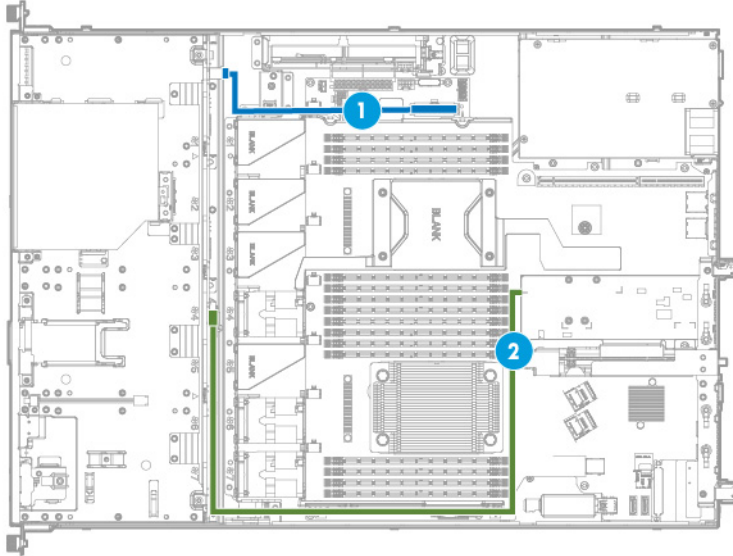
Item	Description
1	Drive power cable
2	Mini-SAS cable

- Four-bay LFF drive cage connected to a P440 controller in the low-profile expansion slot



Item	Description
1	Drive power cable
2	Mini-SAS cable

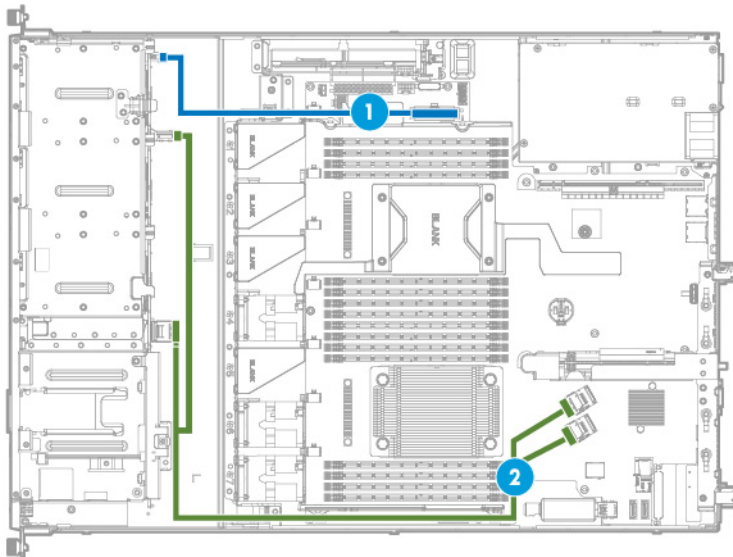
- Four-bay LFF drive cage connected to a H240 adapter in the low-profile expansion slot



Item	Description
1	Drive power cable
2	Mini-SAS cable

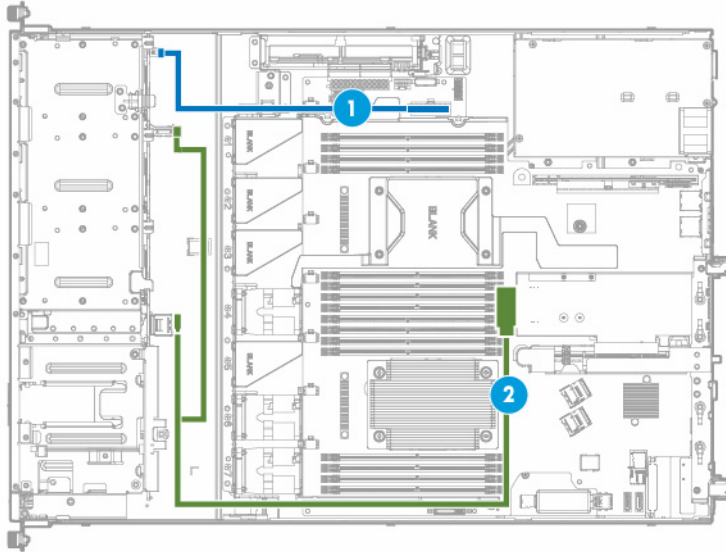
Eight-bay SFF hot-plug drive cabling

- Eight-bay SFF drive cage connected to the system board



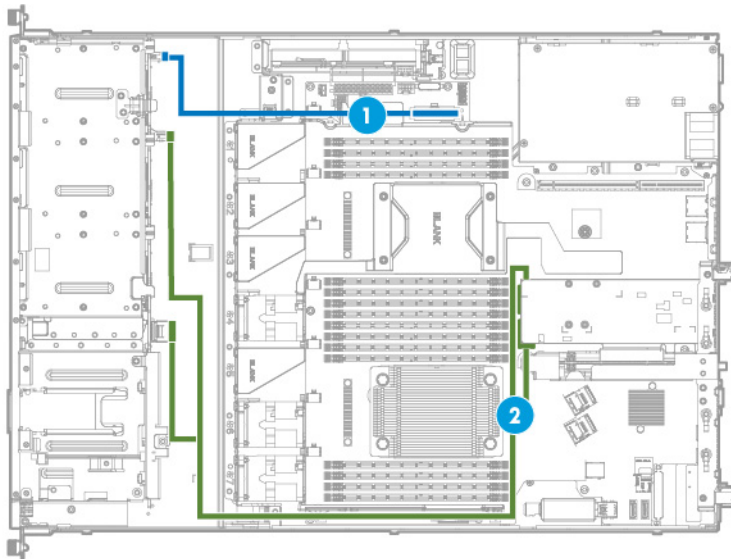
Item	Description
1	Drive power cable
2	Mini-SAS cable

- Eight-bay SFF drive cage connected to a P440 controller in the low-profile expansion slot



Item	Description
1	Drive power cable
2	Mini-SAS cable

- Eight-bay SFF drive cage connected to a H240 adapter in the low-profile expansion slot



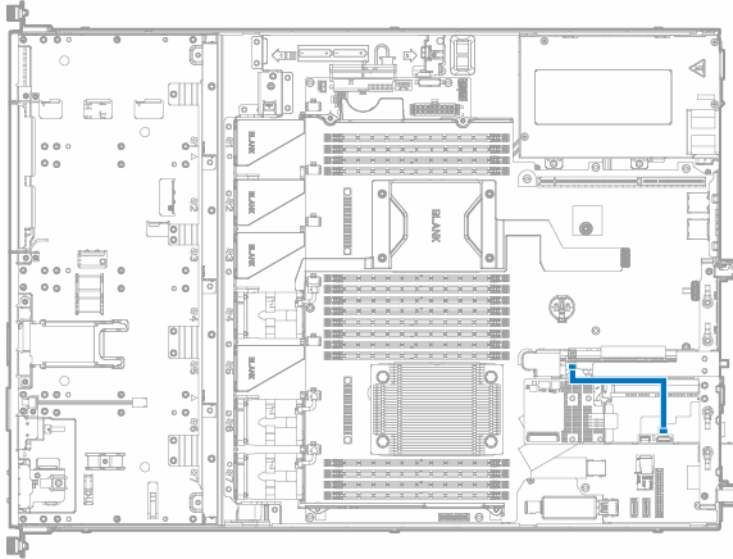
Item	Description
1	Drive power cable
2	Mini-SAS cable

FBWC cabling

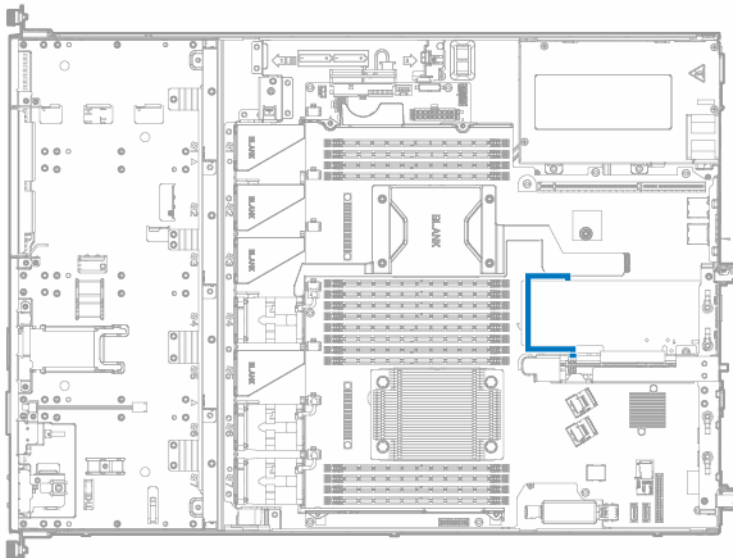
The FBWC solution is a separately purchased option. This server only supports FBWC module installation when an HP Smart Array P-Series controller is installed.

Depending on the controller option installed, the actual storage controller connectors might look different from what is shown in this section.

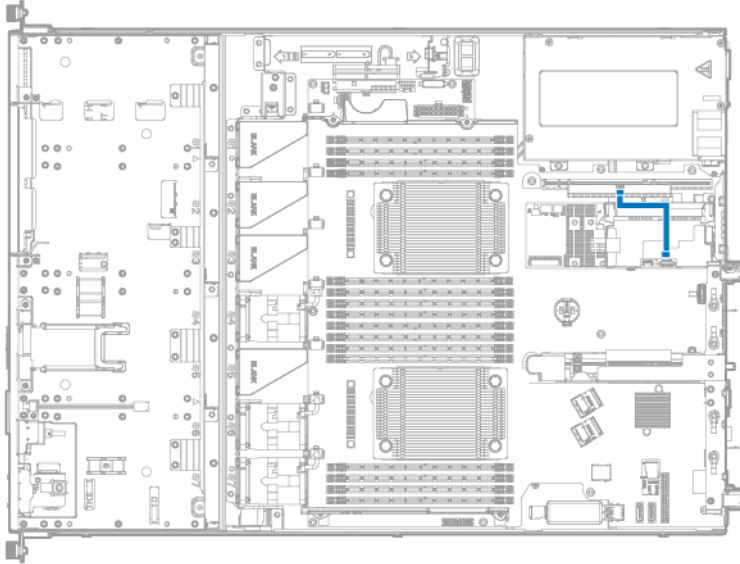
- FBWC module slot 1 cabling



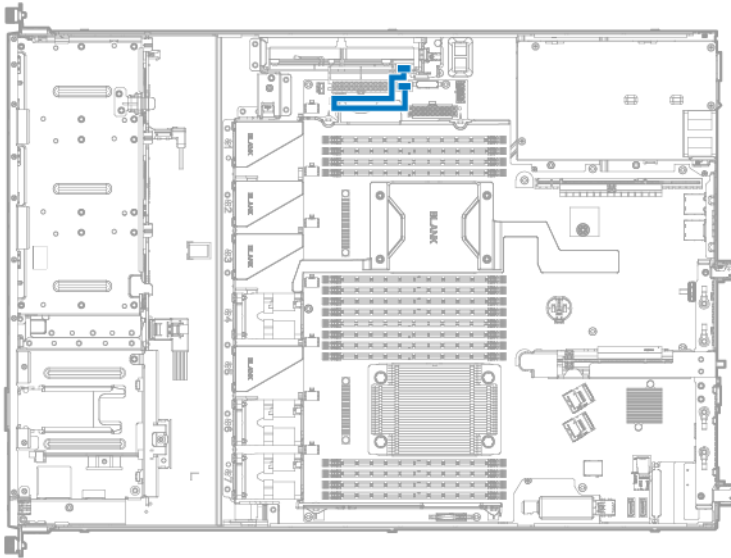
- FBWC module slot 2 cabling



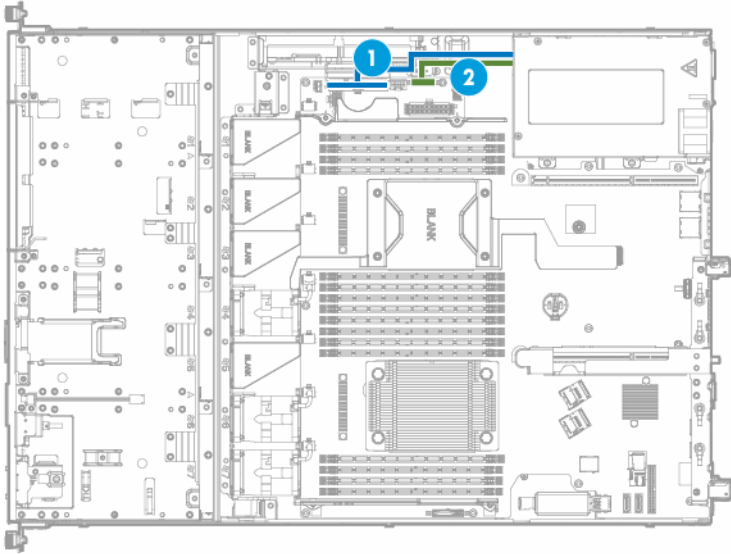
- FBWC module slot 3 cabling



HP Smart Storage Battery cabling



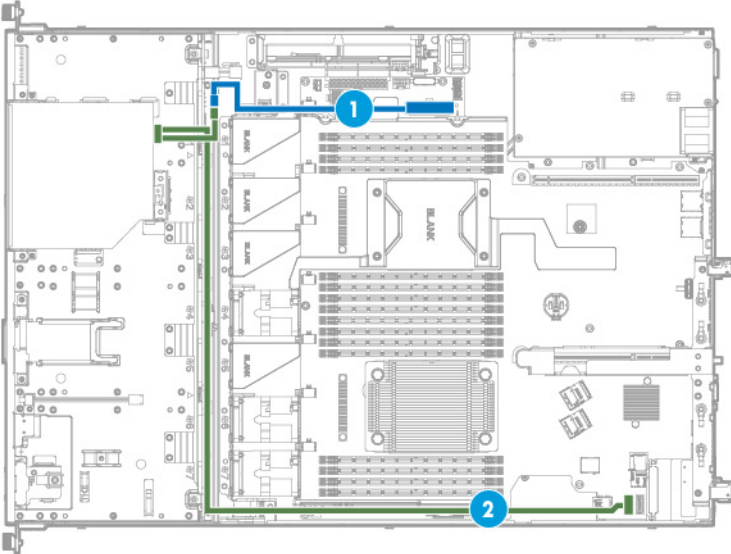
HP 550W Power Supply cabling (non-hot plug)



Item	Description
1	24-pin power supply cable
2	16-pin power supply sideband signal cable

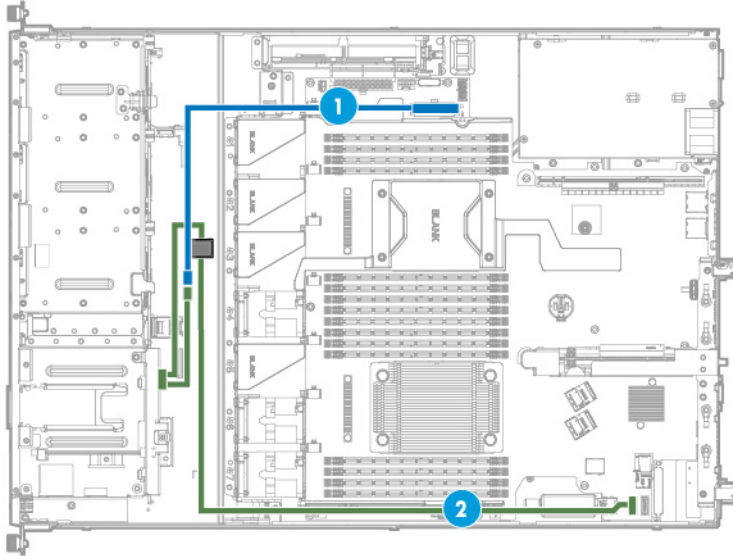
Optical drive cabling

- Optical drive cabling in the four-bay LFF drive configuration



Item	Description
1	Drive power cable
2	Optical drive cable

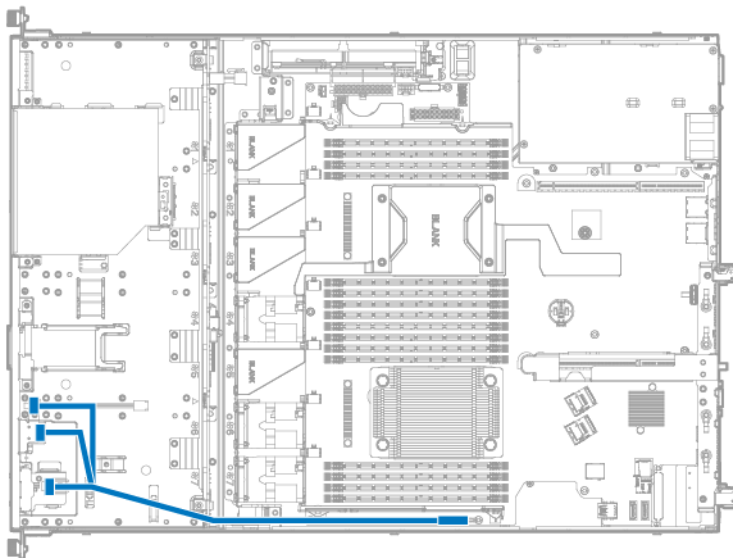
- Optical drive cabling in the eight-bay SFF drive configuration



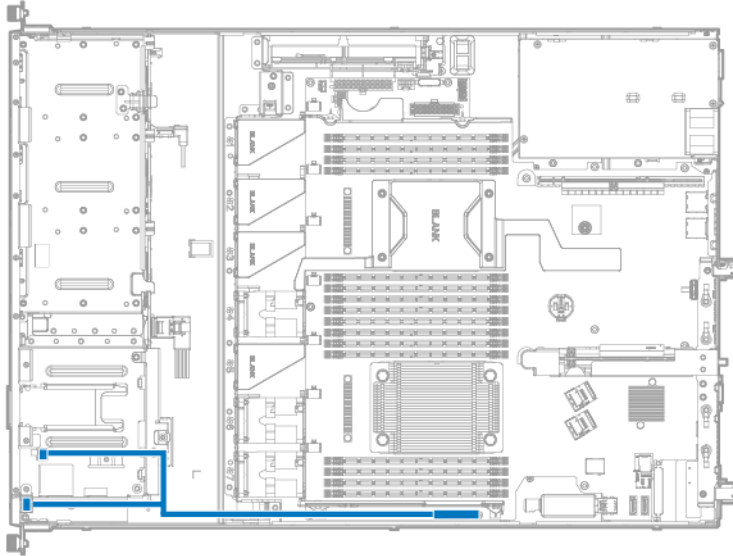
Item	Description
1	Drive power cable
2	Optical drive cable

Front I/O cabling

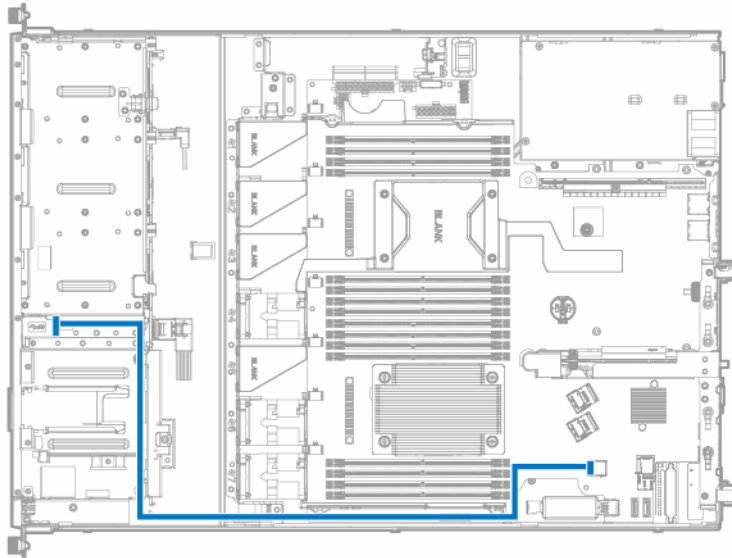
- Front I/O cabling in LFF configuration



- Front I/O cabling in SFF configuration



Front USB 3.0 cabling



Specifications

Environmental specifications

Specification	Value
Temperature range*	—
Operating	10°C to 35°C (50°F to 95°F)
Nonoperating	-30°C to 60°C (-22°F to 140°F)
Relative humidity (noncondensing)	—
Operating	Minimum to be the higher (more moisture) of -12°C (10.4°F) dew point or 8% relative humidity Maximum to be 24°C (75.2°F) dew point or 90% relative humidity
Nonoperating	5% to 95% 38.7°C (101.7°F), maximum wet bulb temperature

* All temperature ratings shown are for sea level. An altitude derating of 1.0°C per 304.8 m (1.8°F per 1000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed. Maximum rate of change is 20°C per hour (36°F per hour). The upper limit and rate of change might be limited by the type and number of options installed.

For certain approved hardware configurations, the supported system inlet temperature range is extended:

- 5°C to 10°C (41°F to 50°F) and 35°C to 40°C (95°F to 104°F) at sea level with an altitude derating of 1.0°C per every 175 m (1.8°F per every 574 ft) above 900 m (2953 ft) to a maximum of 3048 m (10,000 ft).
- 40°C to 45°C (104°F to 113°F) at sea level with an altitude derating of 1.0°C per every 125 m (1.8°F per every 410 ft) above 900 m (2953 ft) to a maximum of 3048 m (10,000 ft).

The approved hardware configurations for this system are listed on the HP website (<http://www.hp.com/servers/ASHRAE>).

Mechanical specifications

Specification	Value
Height	4.29 cm (1.69 in)
Depth for models with LFF drive cage	60.76 cm (23.92 in)
Depth for models with SFF drive cage	60.76 cm (23.92 in)
Width	43.46 cm (17.11 in)
Weight (approximate range)	10.00 kg to 15.00 kg (22.03 lb to 33.04 lb)

Power supply specifications

The server supports the HP 550-W Power Supply (PN 730941-B21). This is an Entry Level Power Supply product for HP ProLiant servers. For more information about the power supply features, specifications, and compatibility, see the HP website (<http://www.hp.com/go/proliant/powersupply>).



CAUTION: Check the system and power supply input ratings before powering up the server.

Acronyms and abbreviations

ABEND

abnormal end

AC

alternating current

AMP

Advanced Memory Protection

CSR

Customer Self Repair

FBWC

flash-backed write cache

GPU

graphics processing unit

HBA

host bus adapter

HP SIM

HP Systems Insight Manager

Hz

hertz

iLO

Integrated Lights-Out

IML

Integrated Management Log

LFF

large form factor

NMI

nonmaskable interrupt

NVRAM

nonvolatile memory

PCIe

Peripheral Component Interconnect Express

POST

Power-On Self Test

PSU

power supply unit

RBSU

ROM-Based Setup Utility

SAS

serial attached SCSI

SATA

serial ATA

SD

Secure Digital

SFF

small form factor

SPP

HP Service Pack for ProLiant

TPM

Trusted Platform Module

UEFI

Unified Extensible Firmware Interface

UID

unit identification

USB

universal serial bus

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Index

A

access panel 30
Active Health System 69
ambient temperature 90

B

bezel 26

C

cabling, drive 82, 83
cabling, FBWC 85
cabling, not-hot-plug power supply 87
cabling, optical drive 87
cautions 24
CMOS 77
components, front panel 71
components, system board 76
crash dump analysis 78
customer self repair (CSR) 6

D

dedicated iLO management module 52
diagnostic tools 65, 68
dimensions and weight 90
DIMM slot locations 77
DIMMs, removing 41
documentation feedback 95
drive blank 27
drive cabling 81
drive LEDs 79
drive numbering 78

E

electrostatic discharge 23
environmental specifications 90
error messages 64
expansion boards 48
extending server from rack 28

F

fan connectors 38, 40

fan module location 80
fan modules, removal 38, 40
fan population guidelines 38
FBWC cabling 81
FBWC module 35
front I/O module 53
front panel components 71
front panel LEDs 72

G

grounding methods 23
grounding requirements 23

H

health LED 72
heatsink 42
hot-plug drive, removing 30
hot-swap fan 40
HP Insight Diagnostics 68
HP Insight Diagnostics survey functionality 68
HP Smart Storage Battery 34
HP Smart Storage Battery cabling 86
HP Systems Insight Manager (SIM) 68, 70
HP technical support 6
humidity 90

I

illustrated parts catalog 16
iLO account information 71
iLO connector 71
Insight Diagnostics 68
Integrated Lights-Out (iLO) 70
Integrated Management Log (IML) 70
Intelligent Provisioning 65, 68
internal USB connector 76

L

LED, health 72
LED, system power 72, 75
LEDs, drive 79
LEDs, front panel 72
LEDs, NIC 72, 75
LEDs, power fault 73

LEDs, power supply 73
LEDs, unit identification (UID) 72
legacy USB support 70

M

management tools 65
mechanical components 16
mechanical specifications 90
memory dump 78
Mini-SAS cabling 81

N

NIC connectors 71, 74
NMI functionality 78
NMI header 76, 78
non-hot-plug drive blank 27, 29
non-hot-plug power supply cabling 87

O

operating system crash 78
operating systems supported 68
optical drive 36
optical drive cabling 87

P

PCI riser board slot definitions 75
POST error messages 64
power supply LEDs 73
power supply specifications 91
powering down 26
power-on password 77
preparation procedures 25
problem diagnosis 64, 65
processor 44
Product ID 67

Q

QR code label 65, 71

R

rack warnings 25
rear panel components 74
rear panel LEDs 75
redundant fan 38
re-entering the server serial number 67
removal and replacement procedures 23
removing PCI riser cage 75

removing server from rack 29
required tools 23
requirements, environmental 90
riser board 49, 75
ROM-Based Setup Utility (RBSU) 65

S

safety considerations 23
security bezel, removing 26
serial number 67
serial number/iLO information pull tab 71
server specifications 90
server warnings and cautions 24, 25
specifications, environmental 90
specifications, power supply 91
specifications, server 90
static electricity 23
storage controller 81
symbols on equipment 23
system battery 18
system board 18
system board components 76
system components 71
system maintenance switch 77

T

technical support 6
temperature requirements 90
TPM connector 76
troubleshooting resources 64
Trusted Platform Module (TPM) 63

U

UID LED 71, 74
unit identification (UID) 71, 74
USB connector 71
USB support 70

V

video connector 71

W

warnings 24, 25
weight 90